

The LIGO logo consists of several concentric, overlapping circles of varying shades of gray, creating a ripple effect that suggests gravitational waves.

**LIGO**



# **Progress on Cryogenic Test Masses for aLIGO Upgrades**

Brett Shapiro  
Stanford University

# Summary

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- Moving from Advanced LIGO to LIGO III
- LIGO III cryogenic test mass suspensions
- Stanford experiment
- LIGO III simulation
- Lessons learned / changes made
- Future work

# Advanced LIGO Timeline



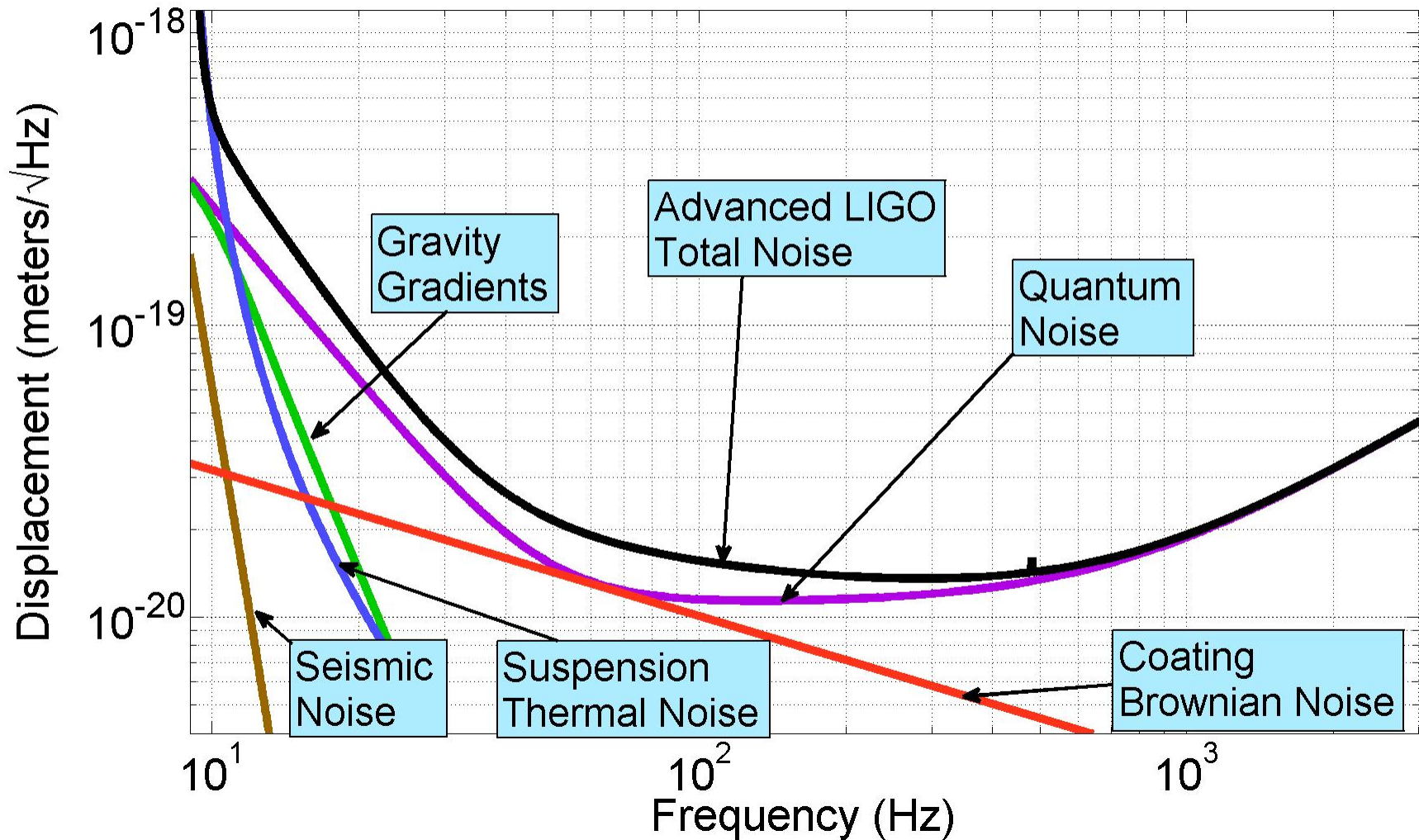
Livingston, LA



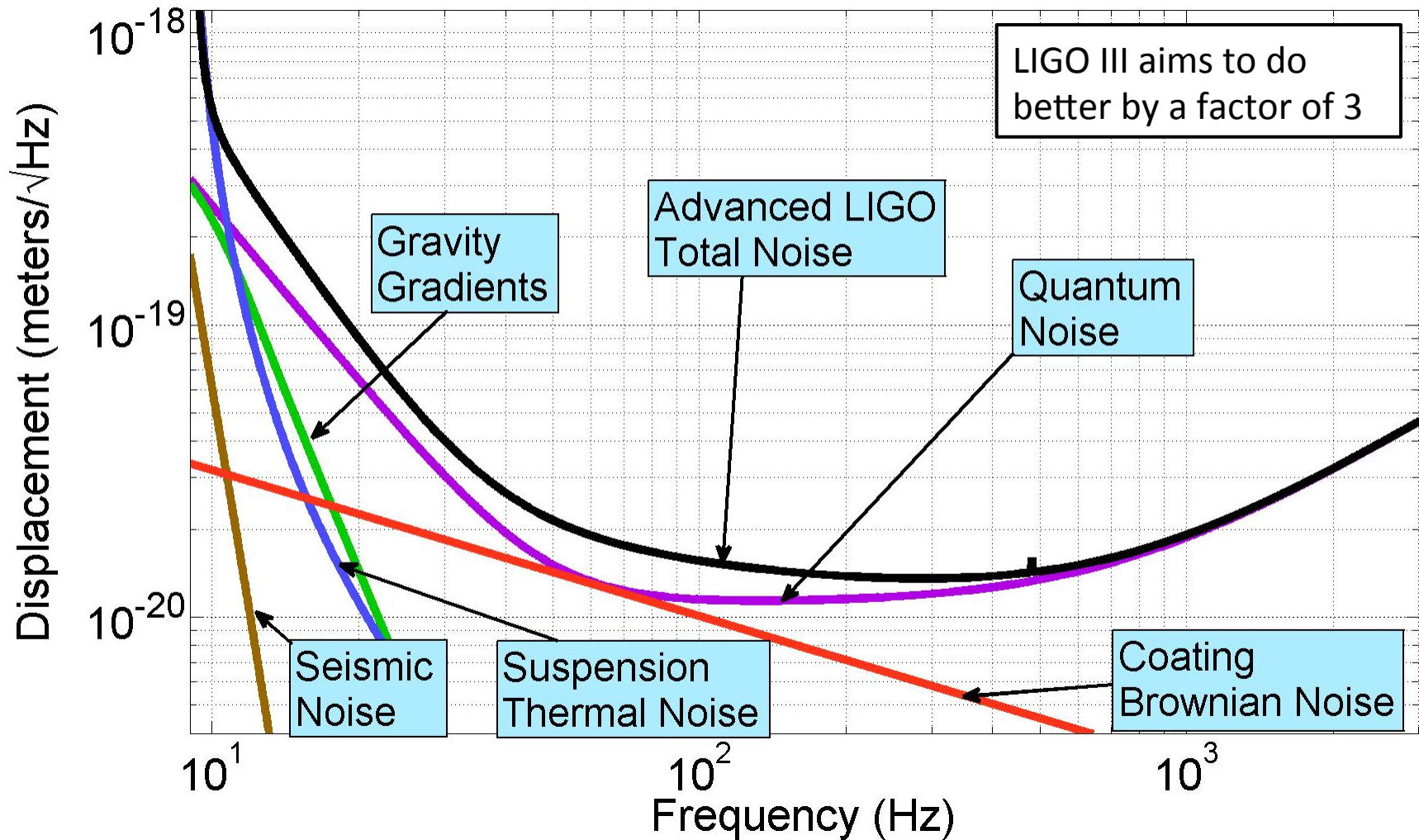
Hanford, WA



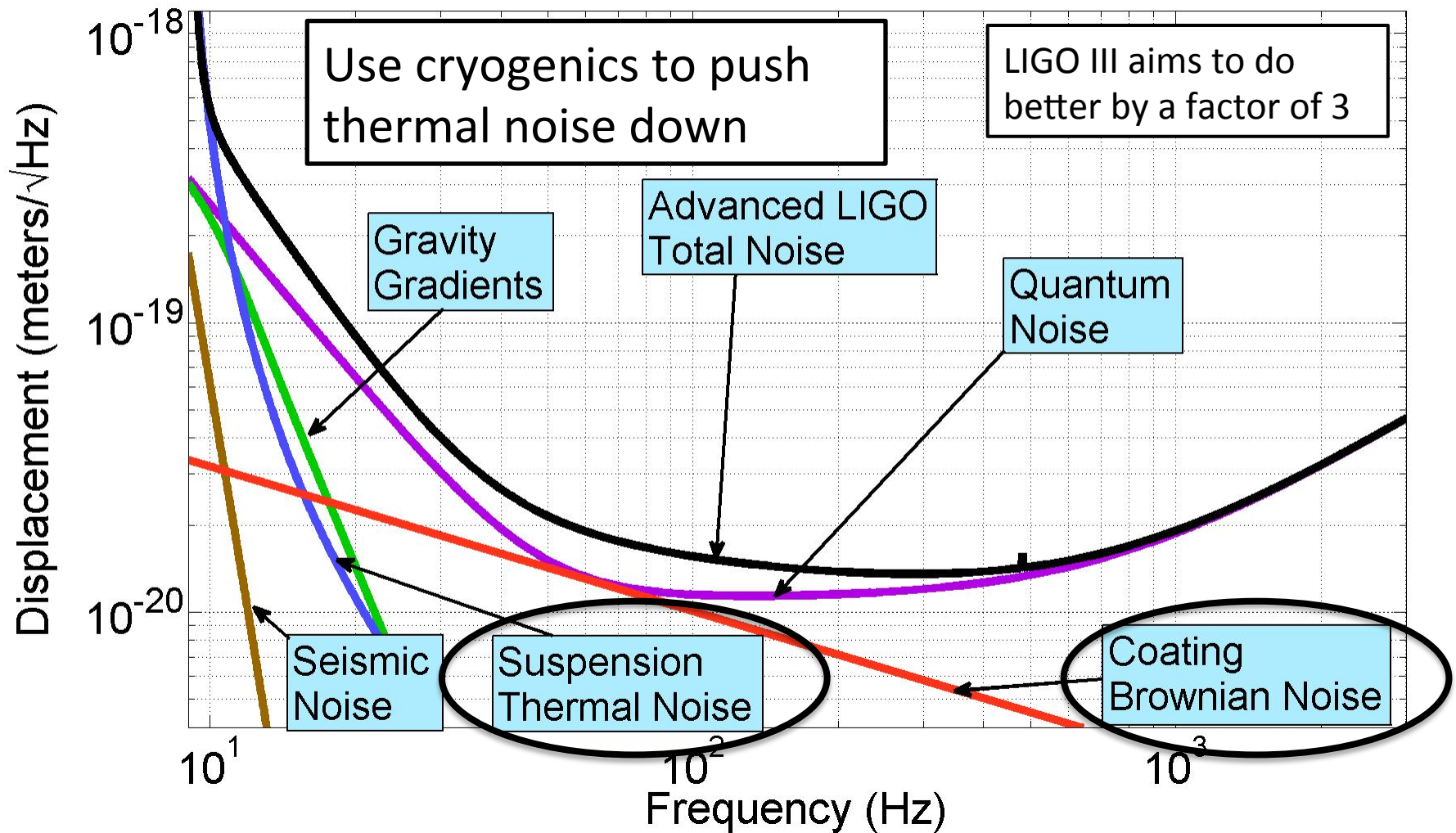
# Predicted Advanced LIGO Sensitivity



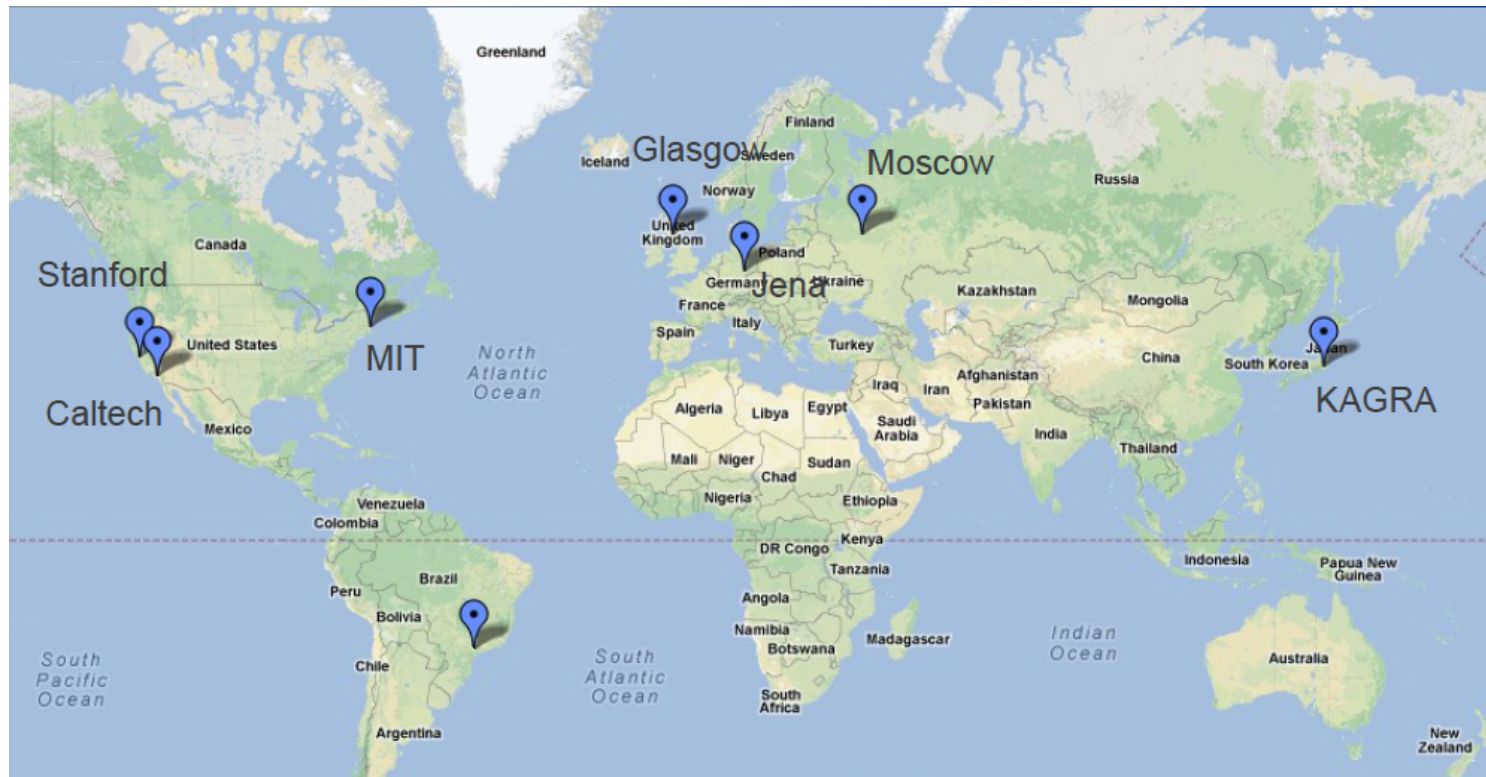
# Predicted Advanced LIGO Sensitivity



# Predicted Advanced LIGO Sensitivity



# LIGO III cryo work distribution



- Caltech - cryogenic reference cavities; direct thermal noise measurements
- Jena/Glasgow/Moscow - mechanical loss
- MIT – high emissivity coatings
- KAGRA – 20 K sapphire suspensions
- INPE Brazil – Cryogenic multi-nested pendulum
- Stanford – optical coatings (Riccardo Bassiri’s talk); cryogenic technology

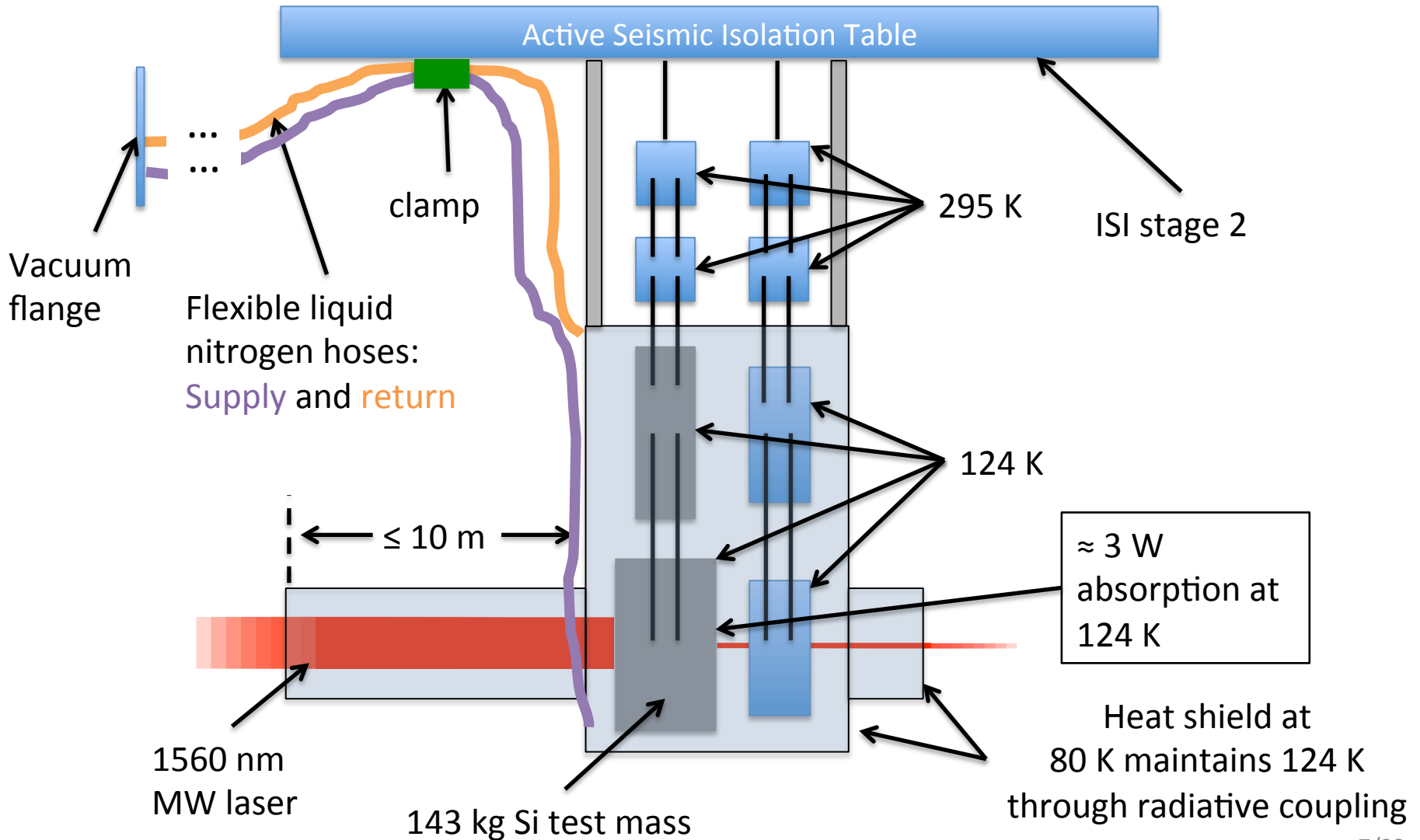
# Cyro Test Mass Problem Statement

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- \* For LIGO III, reduce suspension and coating thermal noise by cooling the lower quad to 124 K (-149.15 C)
  - Si test masses (blue team in LIGO-T1200031)
  - **Get to 124 K in a timely manner** <- Stanford experiment
  - **Then maintain 124 K**
- Include a warm-up scheme (don't forget!)
- Do not increase the test mass lossiness
  - Emissive coatings, heat links, thick sus fibers, optical coatings, substrate, suspension fiber bonding, etc
- Do not compromise passive seismic isolation
  - Cables, hoses, links, etc
- The same seismic isolation platforms (ISIs, HEPIs)
  - Limit the amount of extra weight on these platforms
  - Leave the rest of the vacuum chamber warm



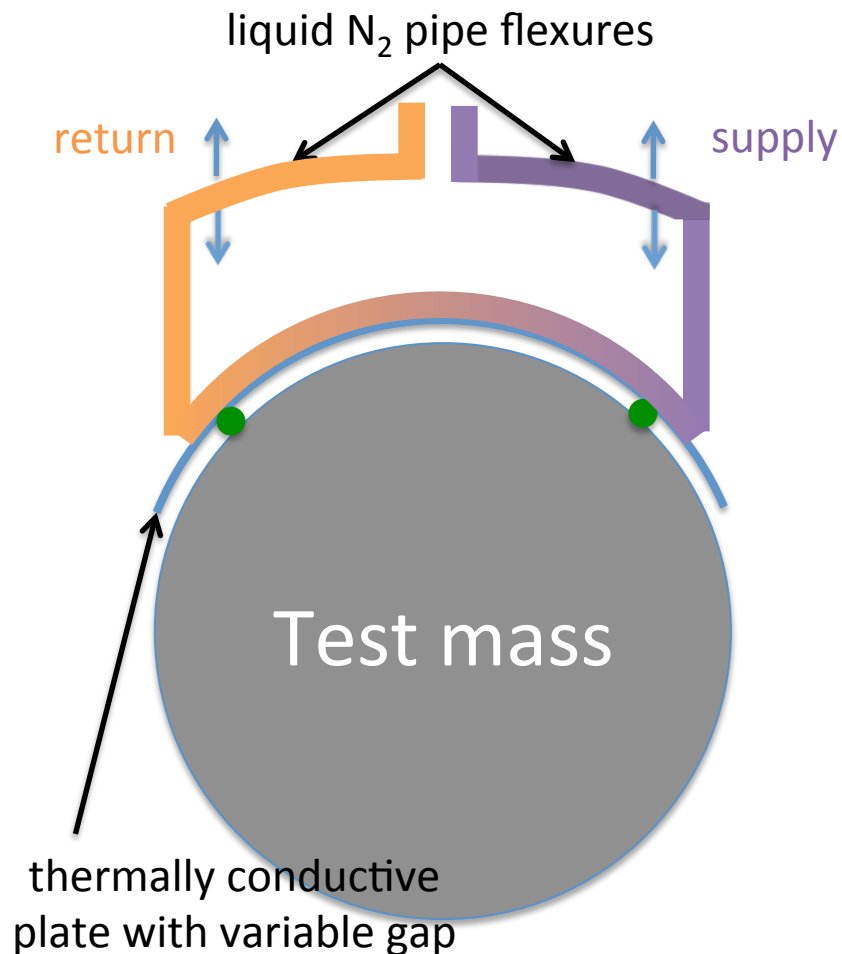
# LIGO III Steady State Cooling



# Initial Cool Down Cold Link – 2 Designs

Conductive cooling, low pressure N<sub>2</sub> gas

Pros and Cons



## Pros

- Operates in partial vacuum.
- Low heat transfer between cold and warm parts of vacuum system.
- Fine temperature control – just back away when at desired temperature
- Versatility, design permits both conductive and convective cooling.

## Cons

- Requires moving parts:
  - flexible pipes
  - actuators
- Physically contacts barrel of test mass

# Initial Cool Down Cold Link – 2 Designs

## Pros and Cons

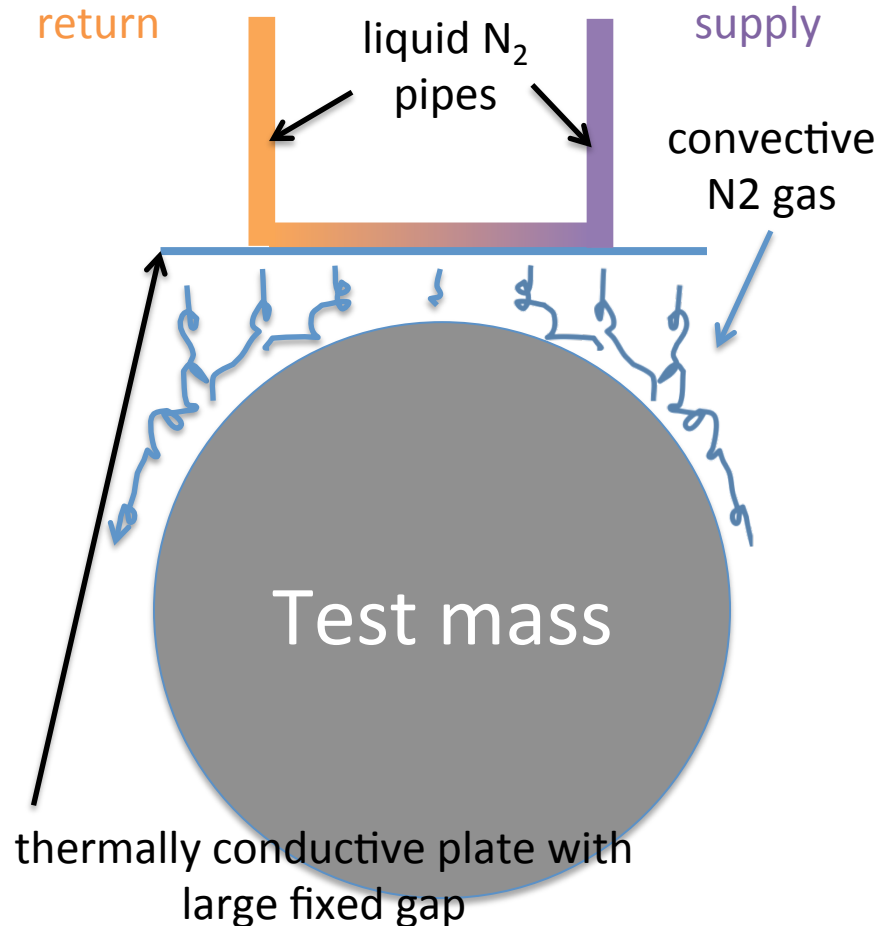
### Pros

- No moving parts or actuators
- No contact with test mass
- Faster cooling than conduction

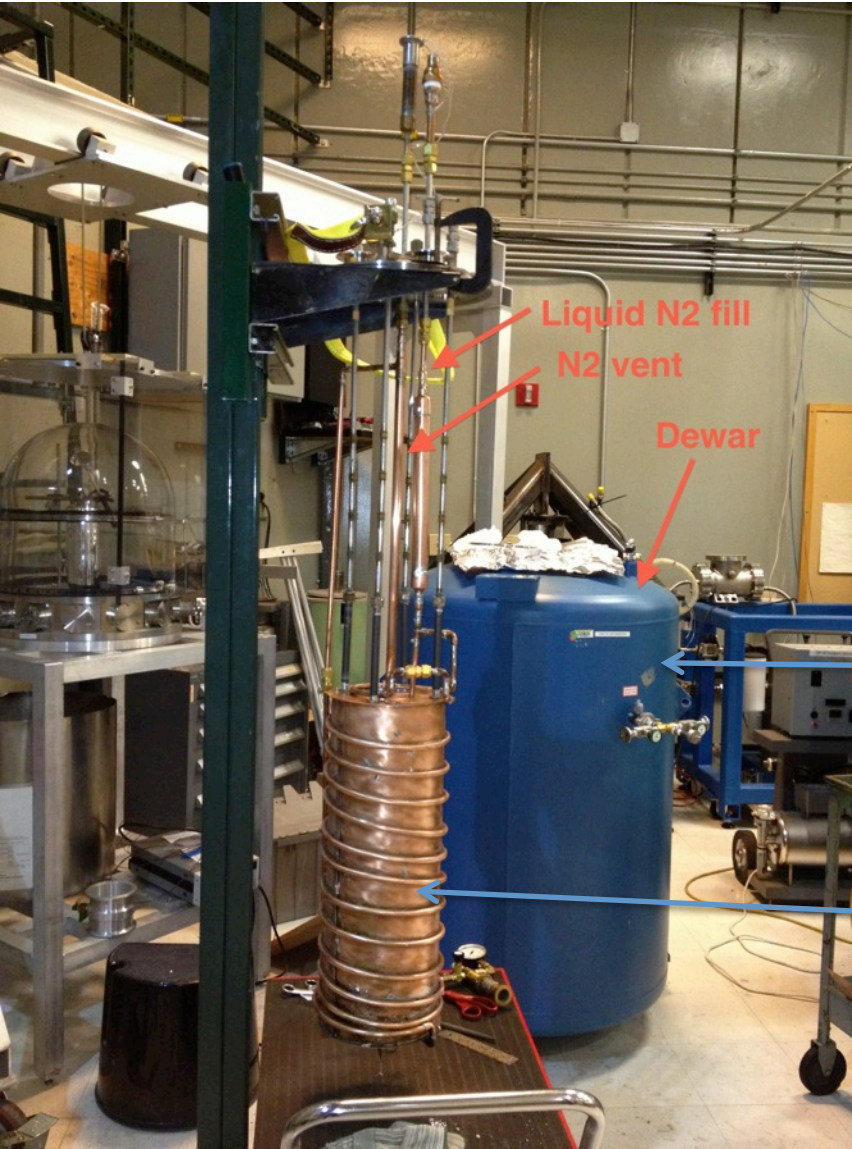
### Cons

- Convection between cold and warm parts of vacuum system
- No fine temperature control – must return to vacuum to ‘turn off’ cold link.
- Does not operate under vacuum

Convective cooling, up to 1 atm N<sub>2</sub> gas

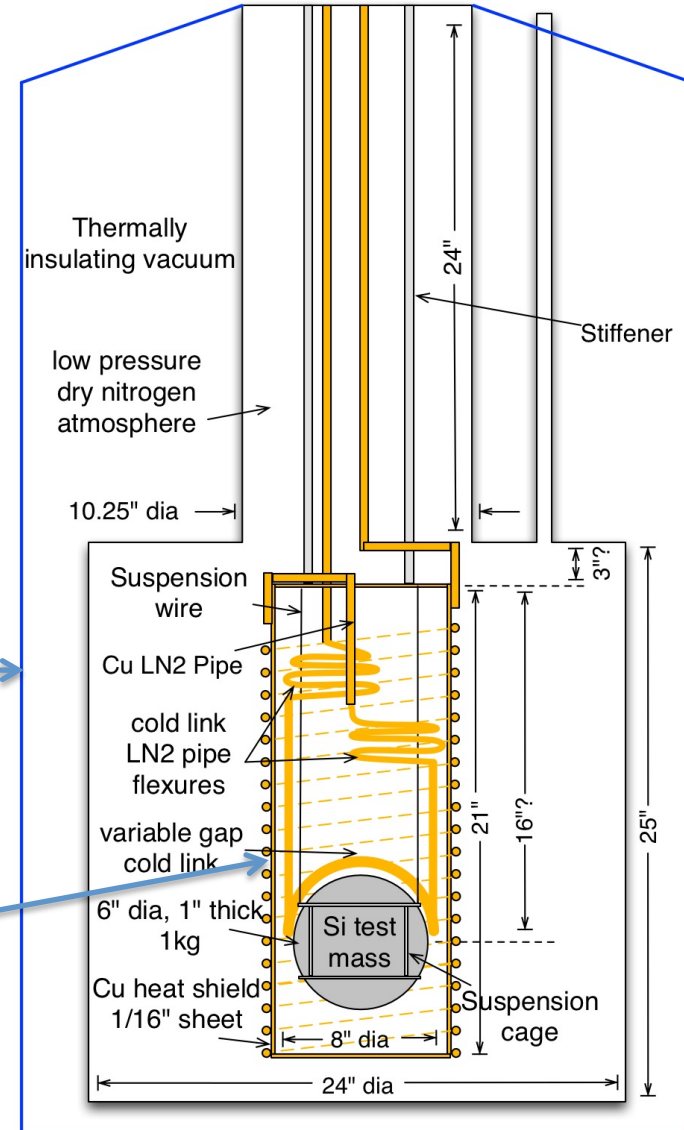


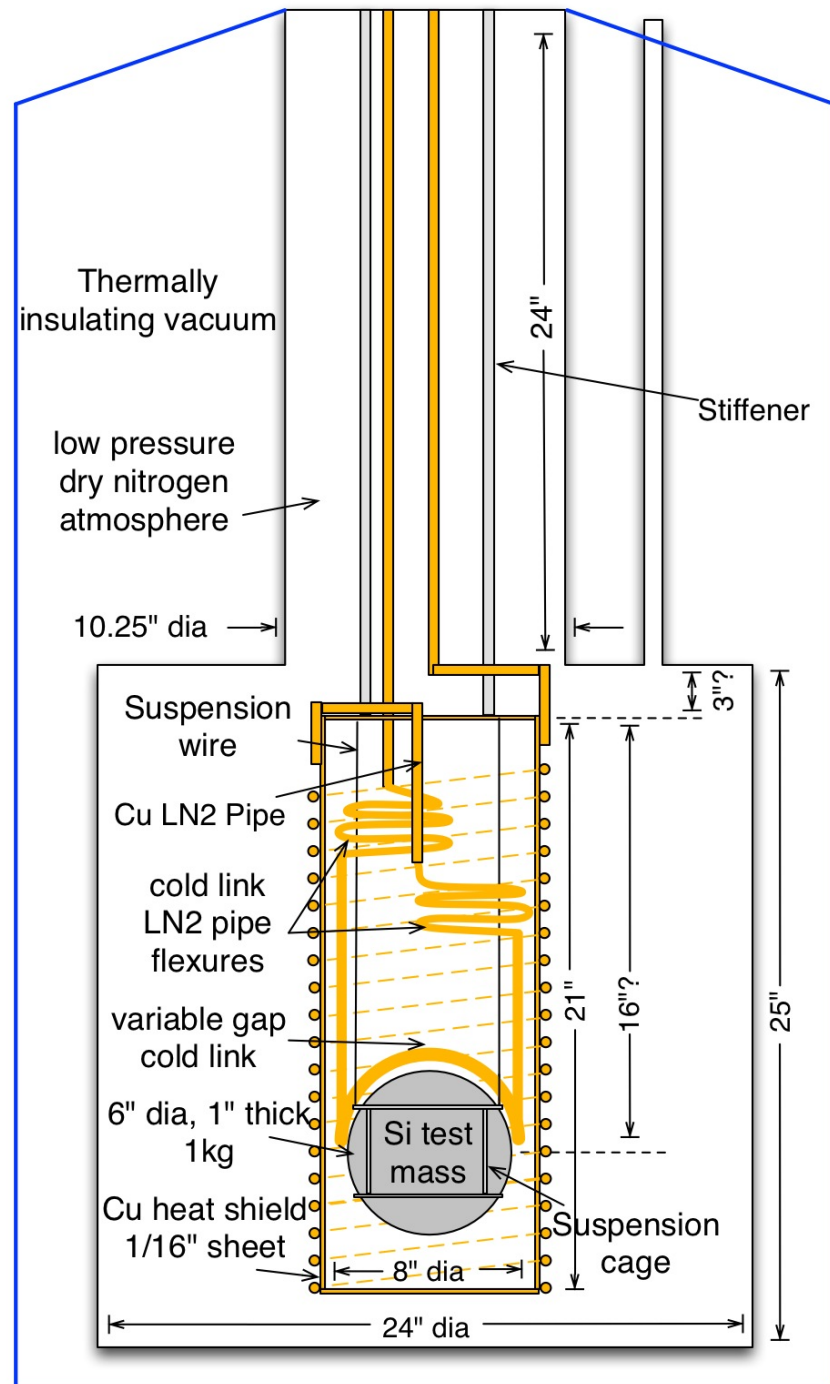
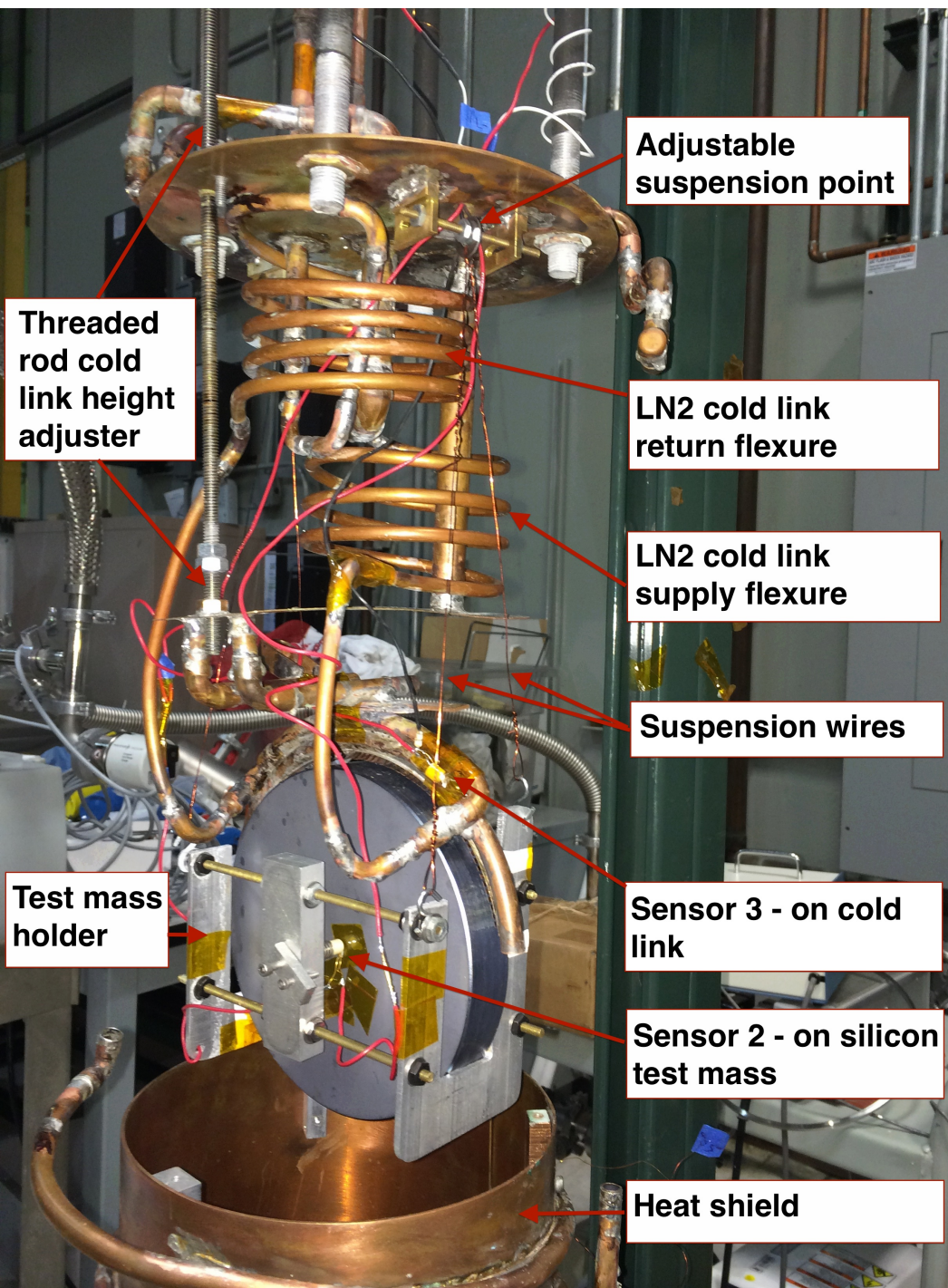
# Experimental Setup



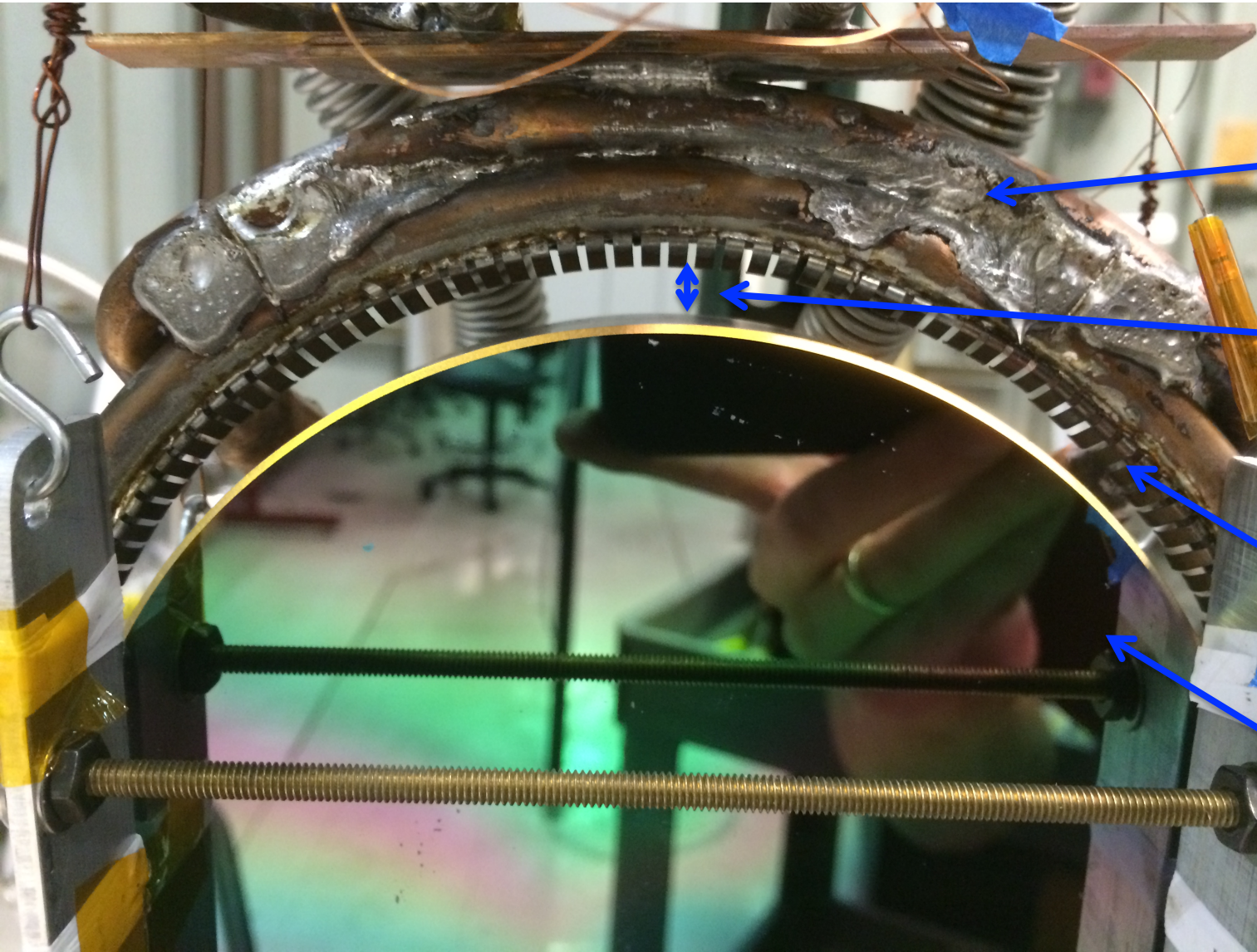
Test dewar

Heat shield





# Close up of cold link



Cold link

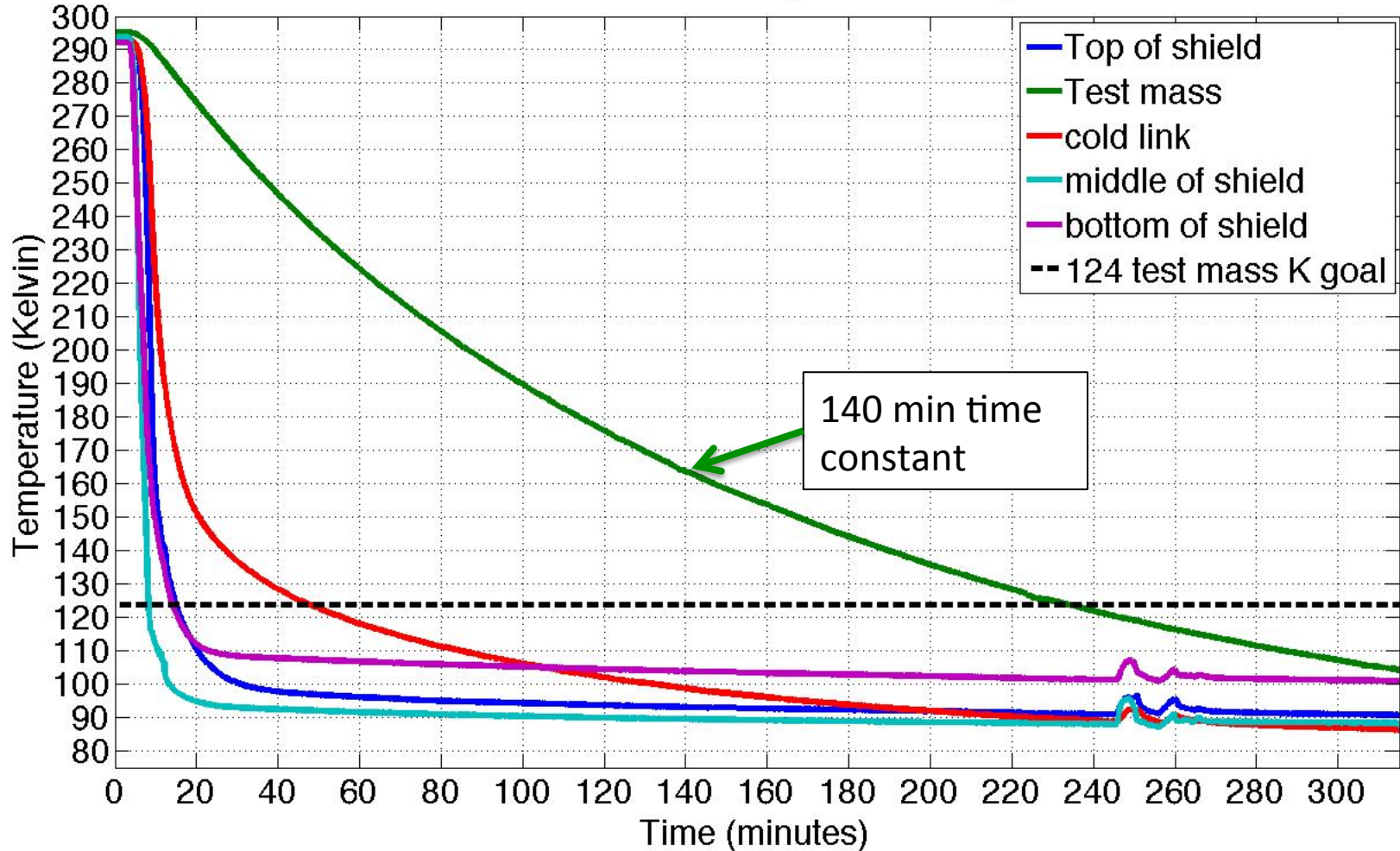
Variable gap

Flexure 'point' contacts

Test mass

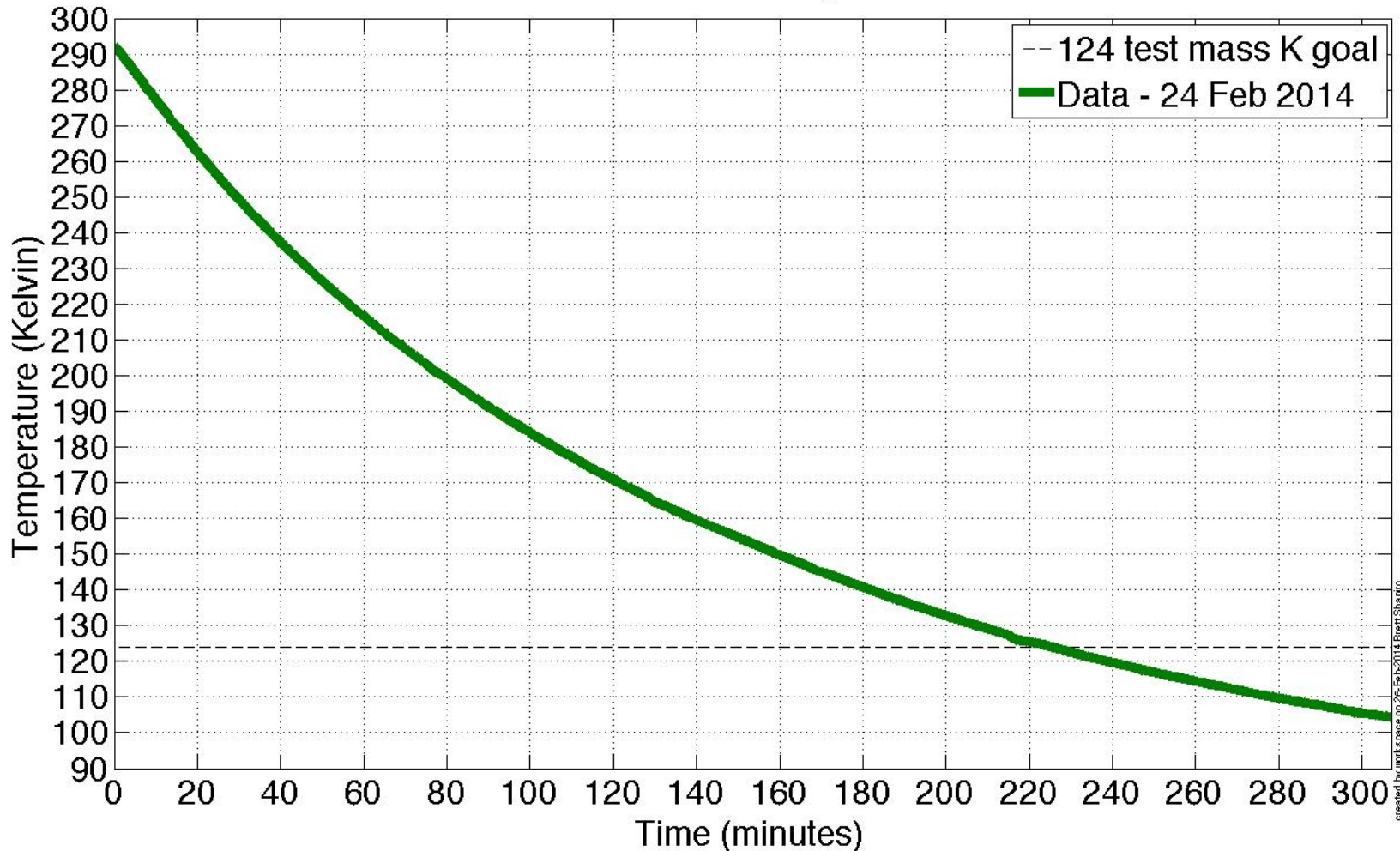
# Measurement – cold link engaged

Silicon Test Mass Cooling - 24 February 2014



# Test mass temperature modeling

Silicon Test Mass Cooling with Cold Link

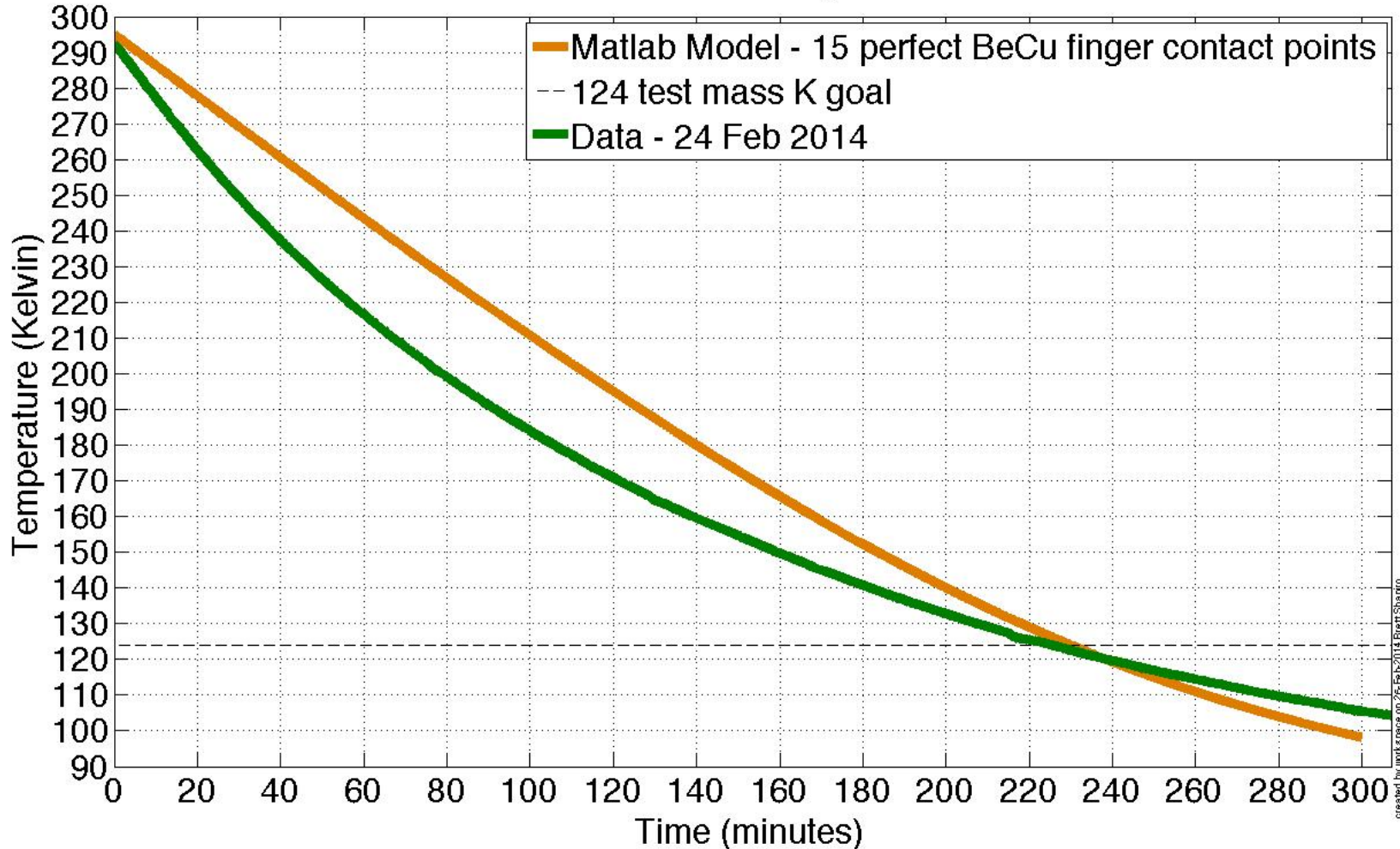


created by work space on 26-Feb-2014 Brent Shapiro



# Test mass temperature modeling

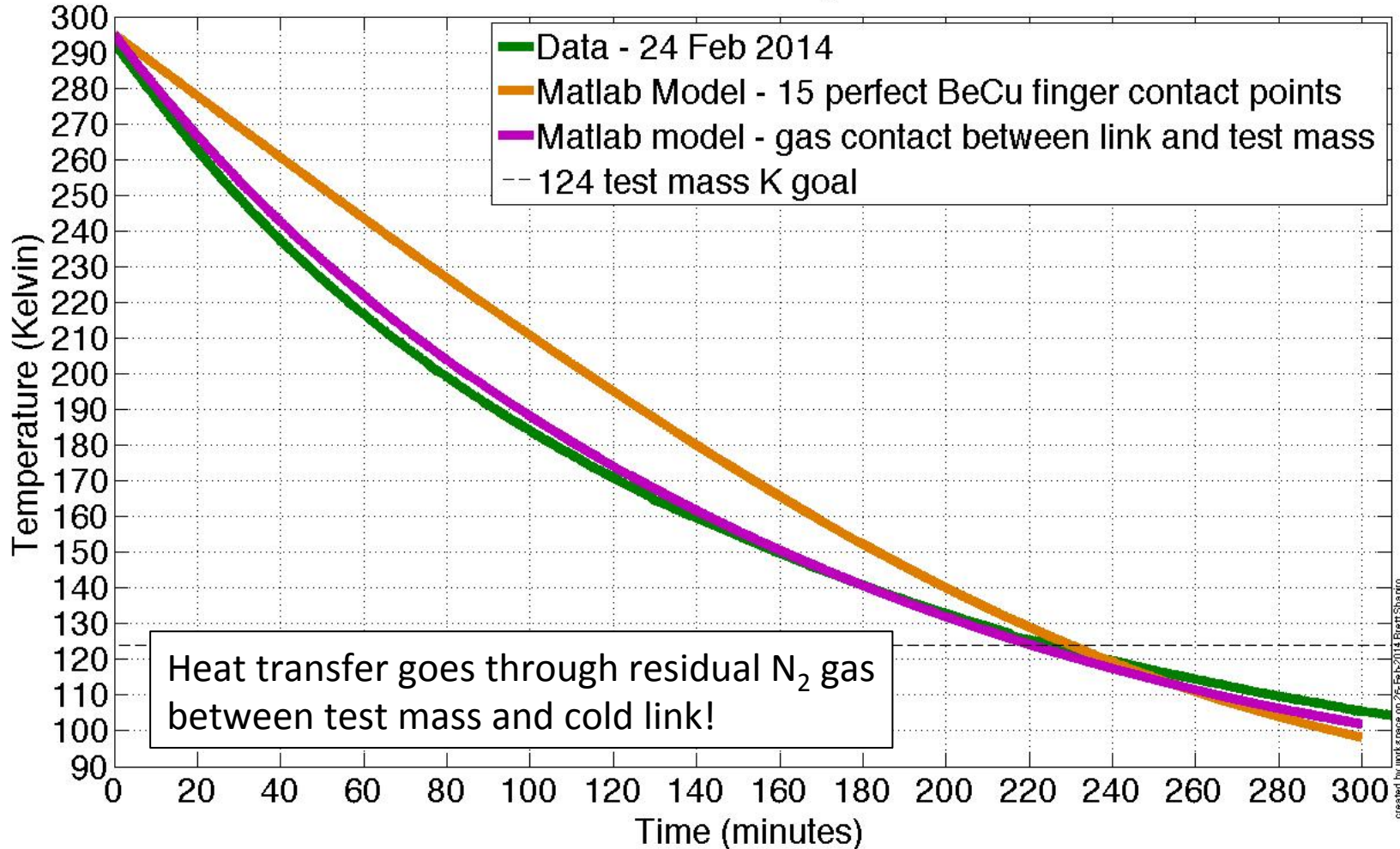
Silicon Test Mass Cooling with Cold Link



created by work space on 26-Feb-2014 Brent Shapiro

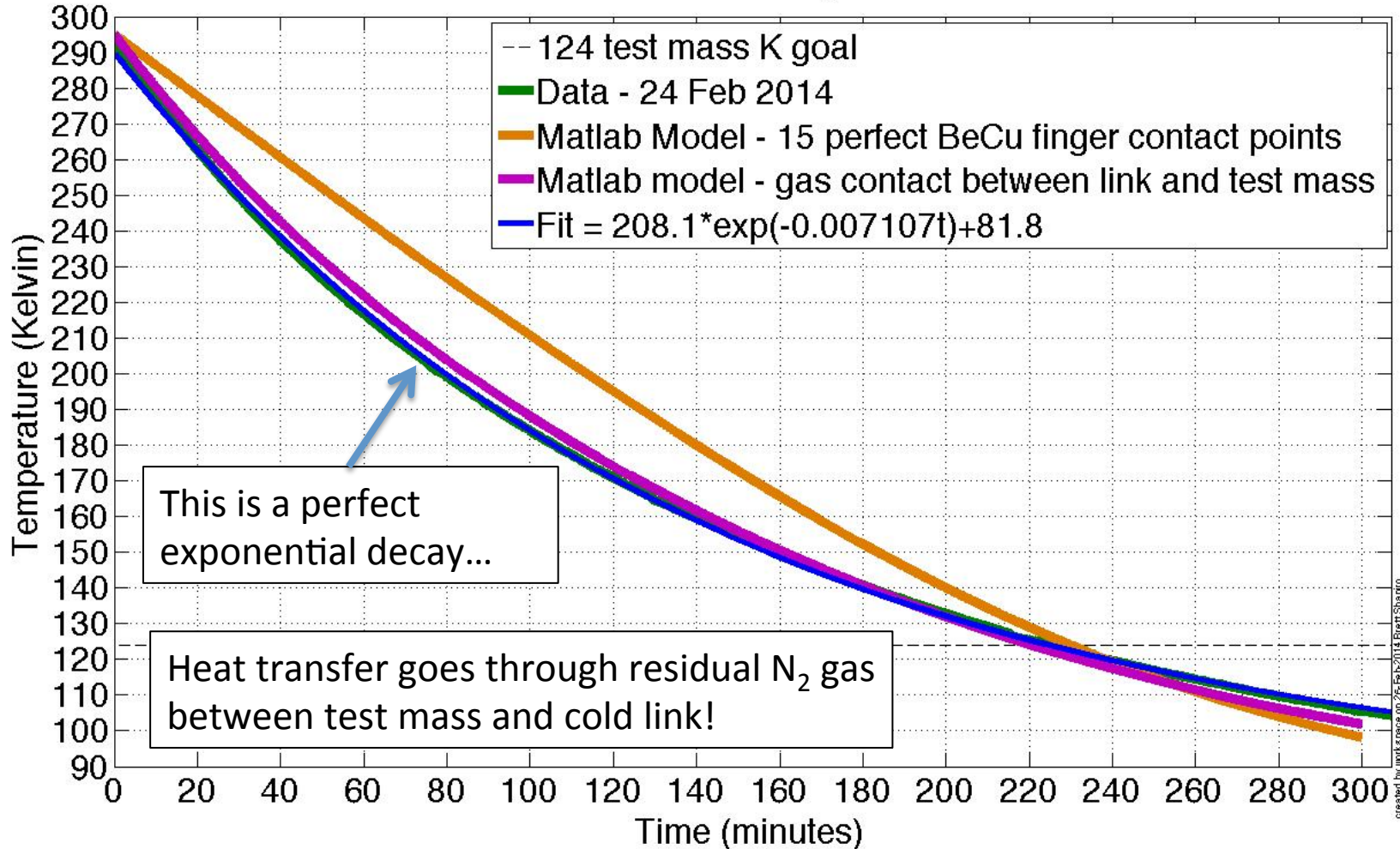
# Test mass temperature modeling

Silicon Test Mass Cooling with Cold Link



# Test mass temperature modeling

Silicon Test Mass Cooling with Cold Link



# Exponential Temperature Decay

$$\dot{T}_{Si} + \frac{K_{CL}}{C_{Si}} T_{Si} = \frac{K_{CL}}{C_{Si}} T_{cold} \quad \longrightarrow \quad T_{Si} = T_{hot} e^{-\frac{K_{CL}t}{C_{Si}}} + T_{cold}$$

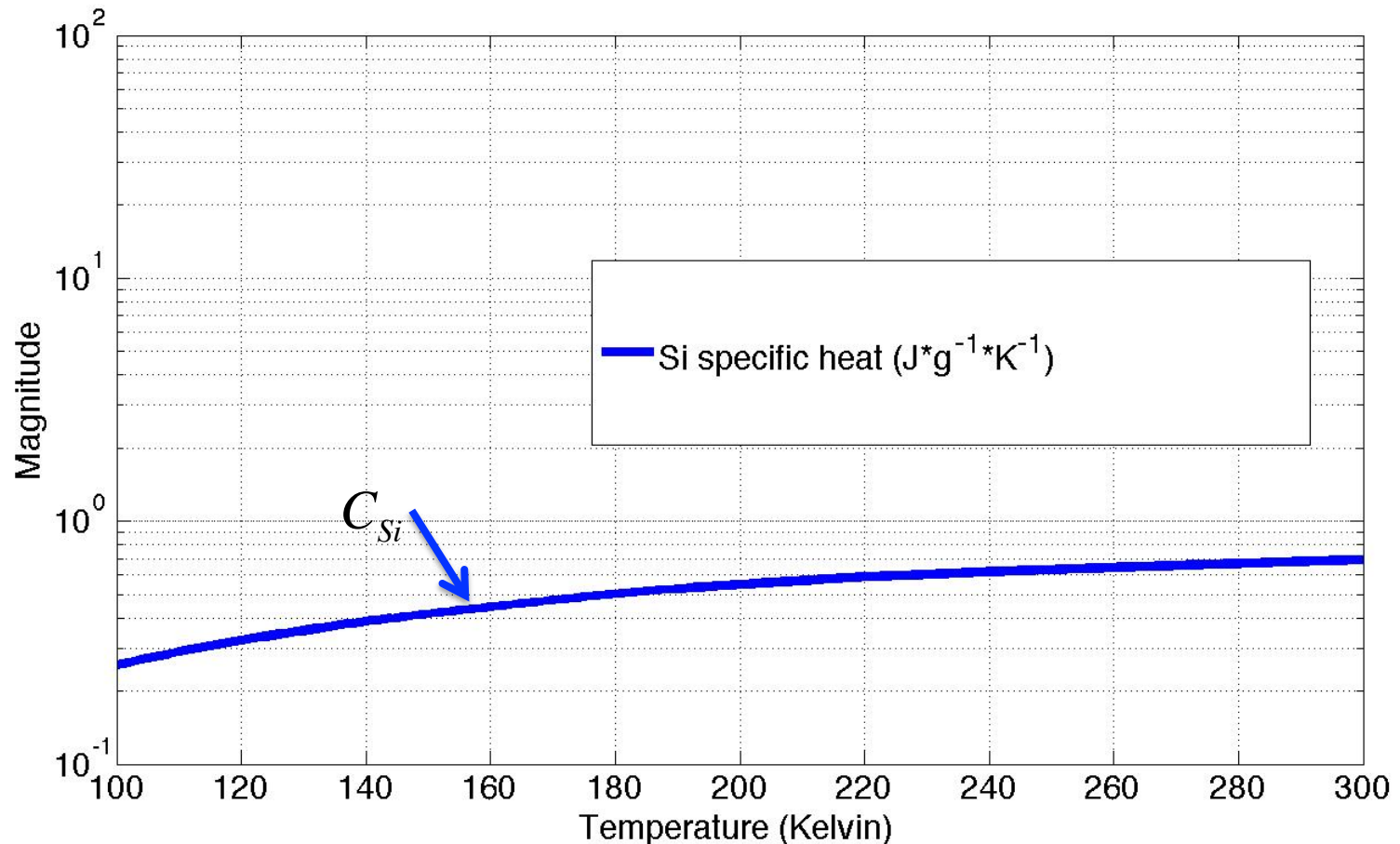
$K_{CL}$  = thermal conductance of cold link

$C_{Si}$  = heat capacity of silicon

- These are both functions of temperature.
- In general, the solution is not truly exponential since the time 'constant' changes.

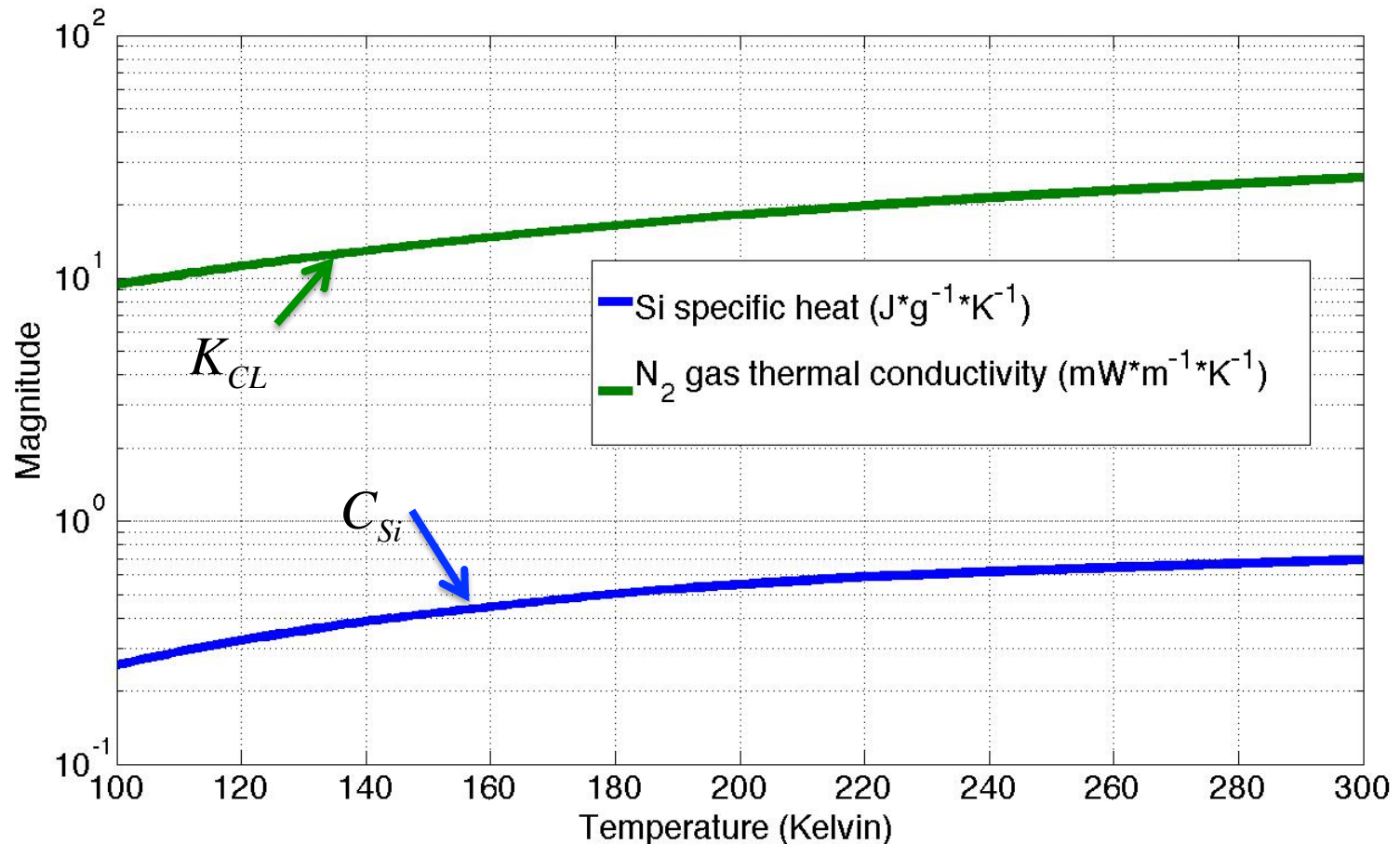
# Exponential Temperature Decay

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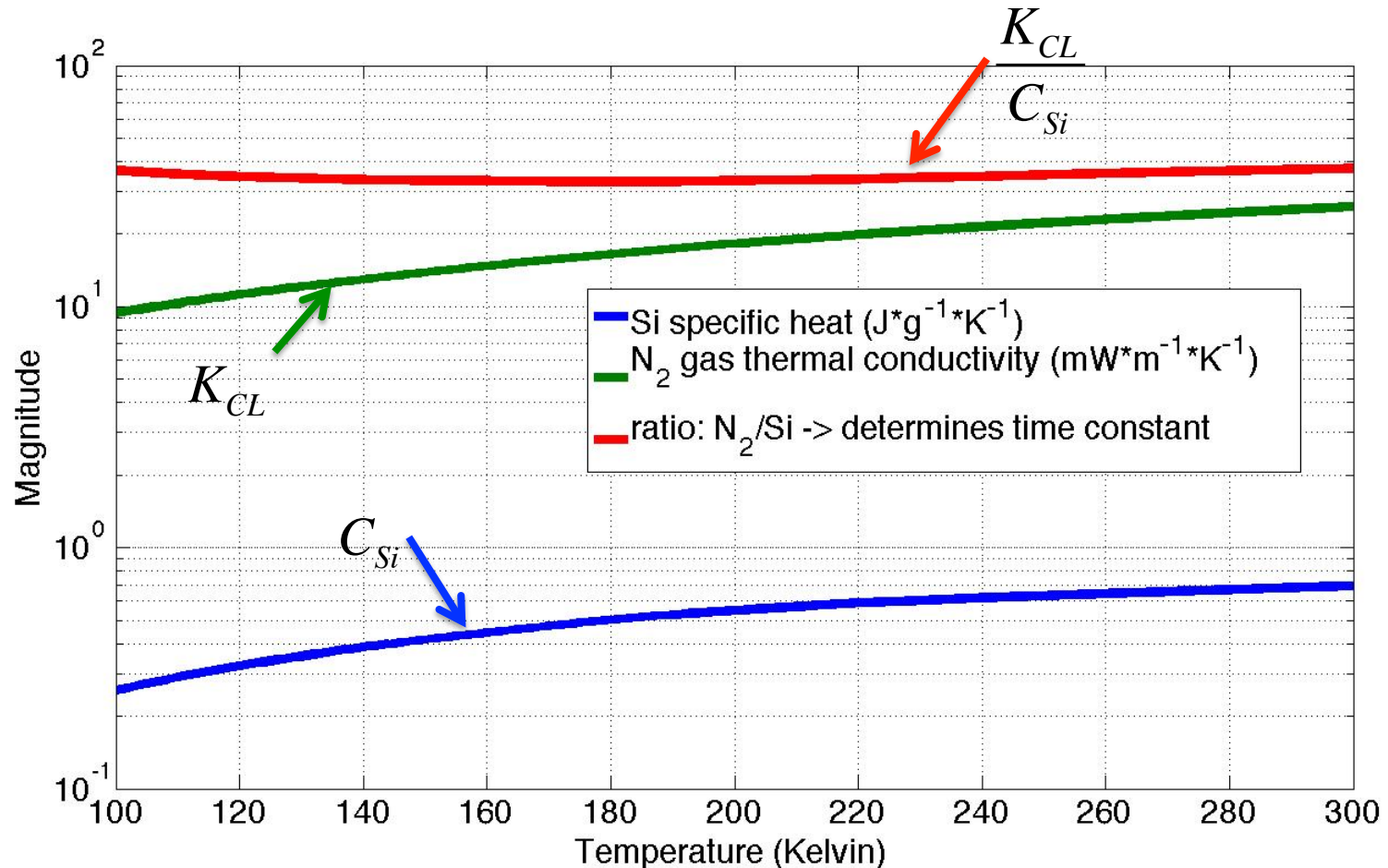
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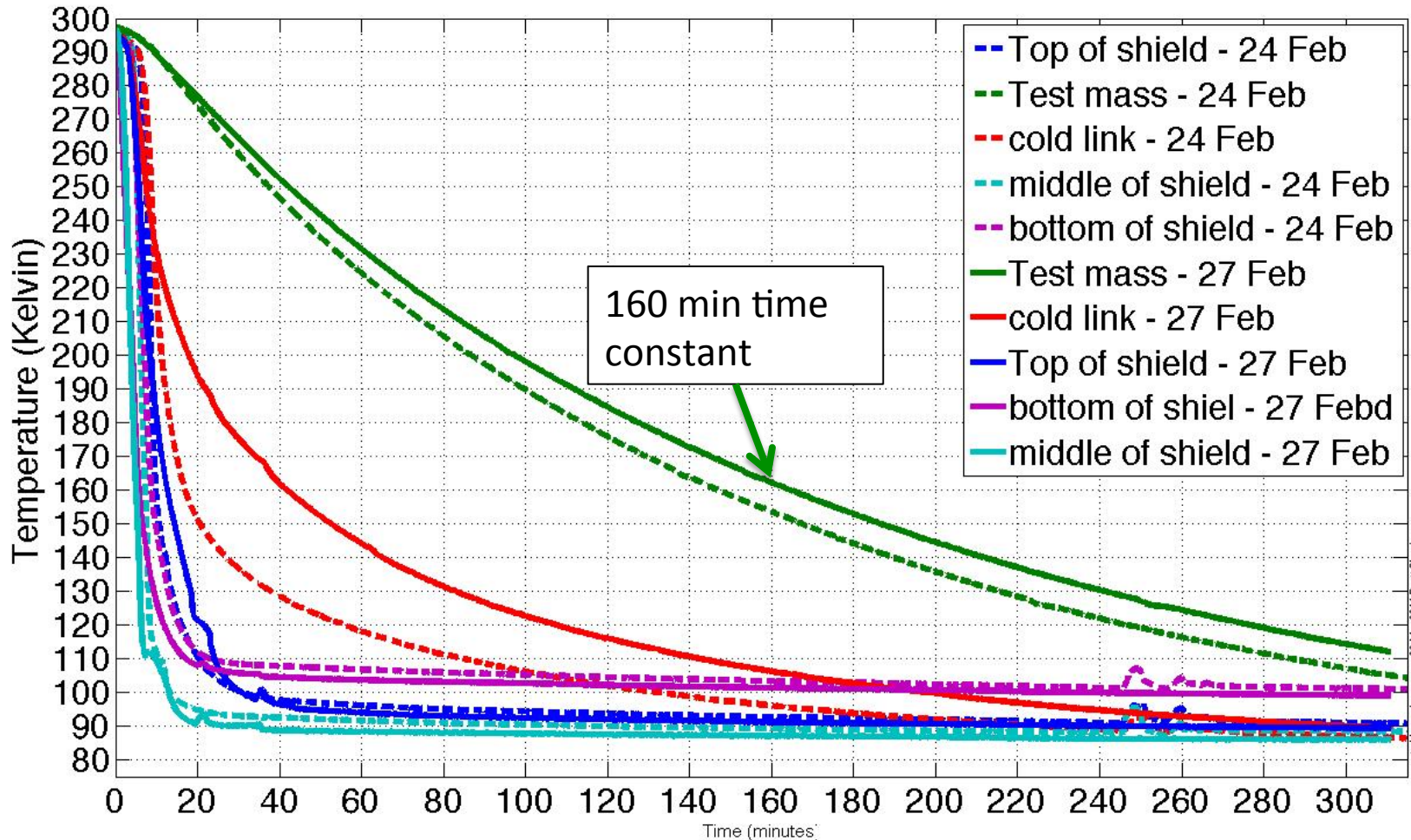
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# Measurement – cold link disengaged

Cold link in contact - 24 Feb; Cold link backed off 0.5 inches - 27 Feb

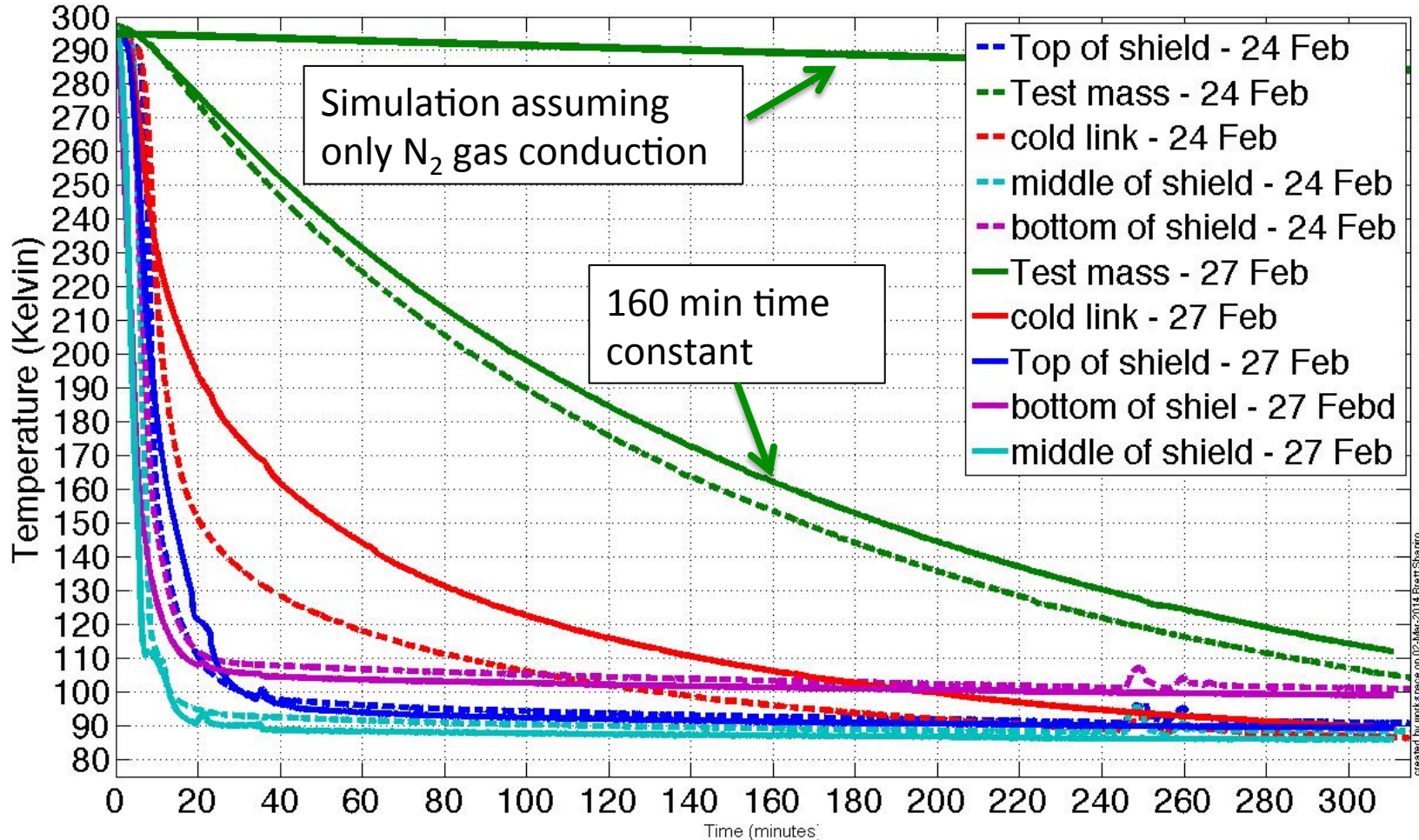


created by workspace on 02-Mar-2014 Brett Shapiro



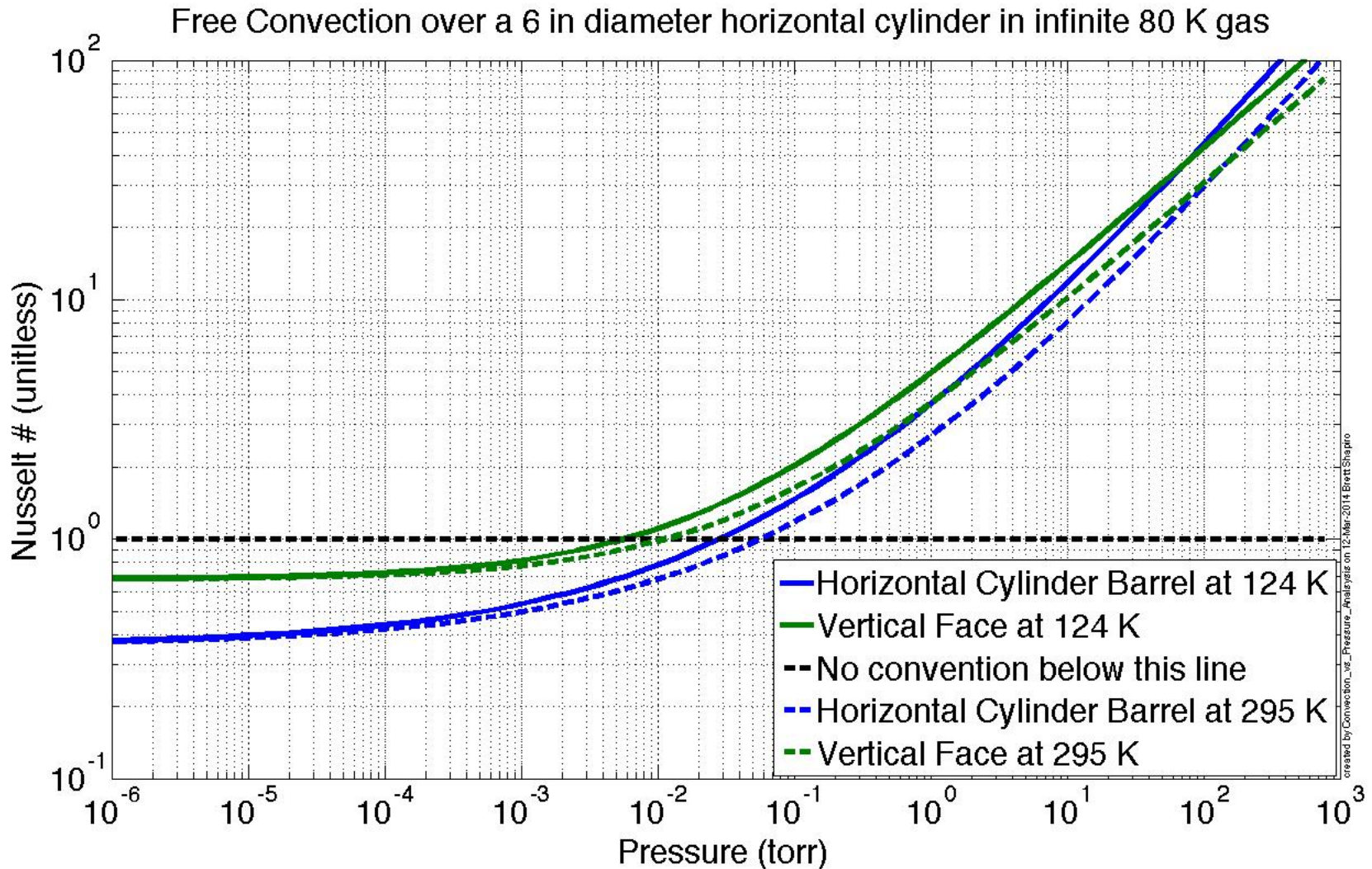
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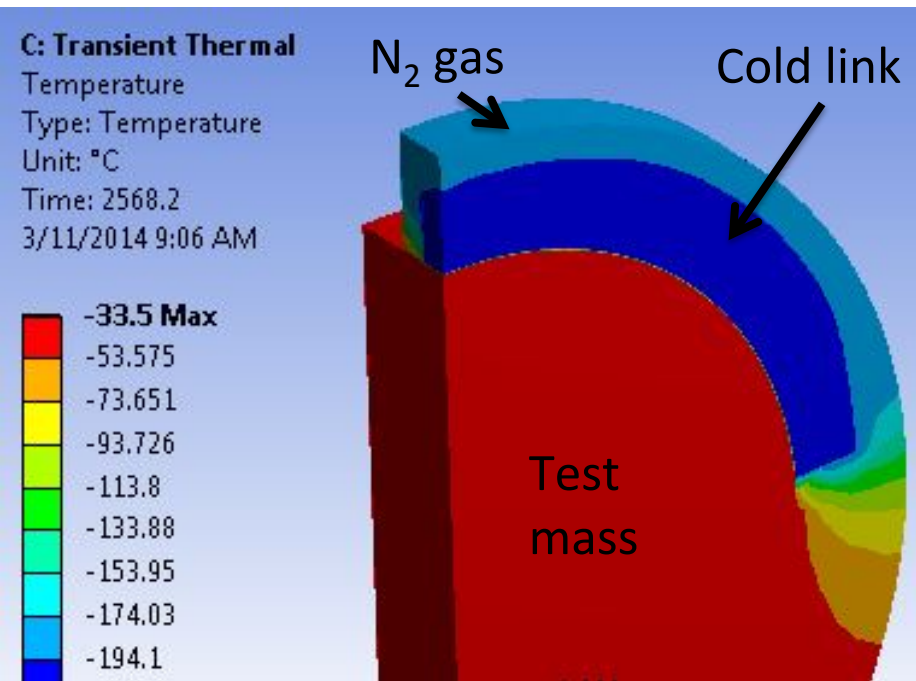
created by workspace on 02-Mar-2014 Brett Shapiro

# Conductive vs Convective Regimes

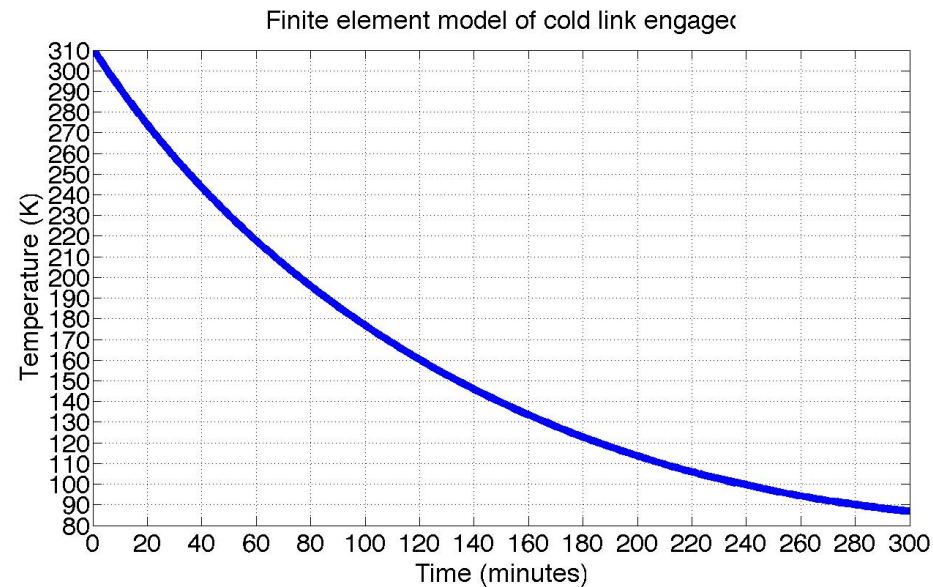


# Finite Element Modeling

- Due to complexity, LIGO III designs must be verified with FEM
- Below: FEM of conduction through  $N_2$  gas to cold link for Stanford experiment



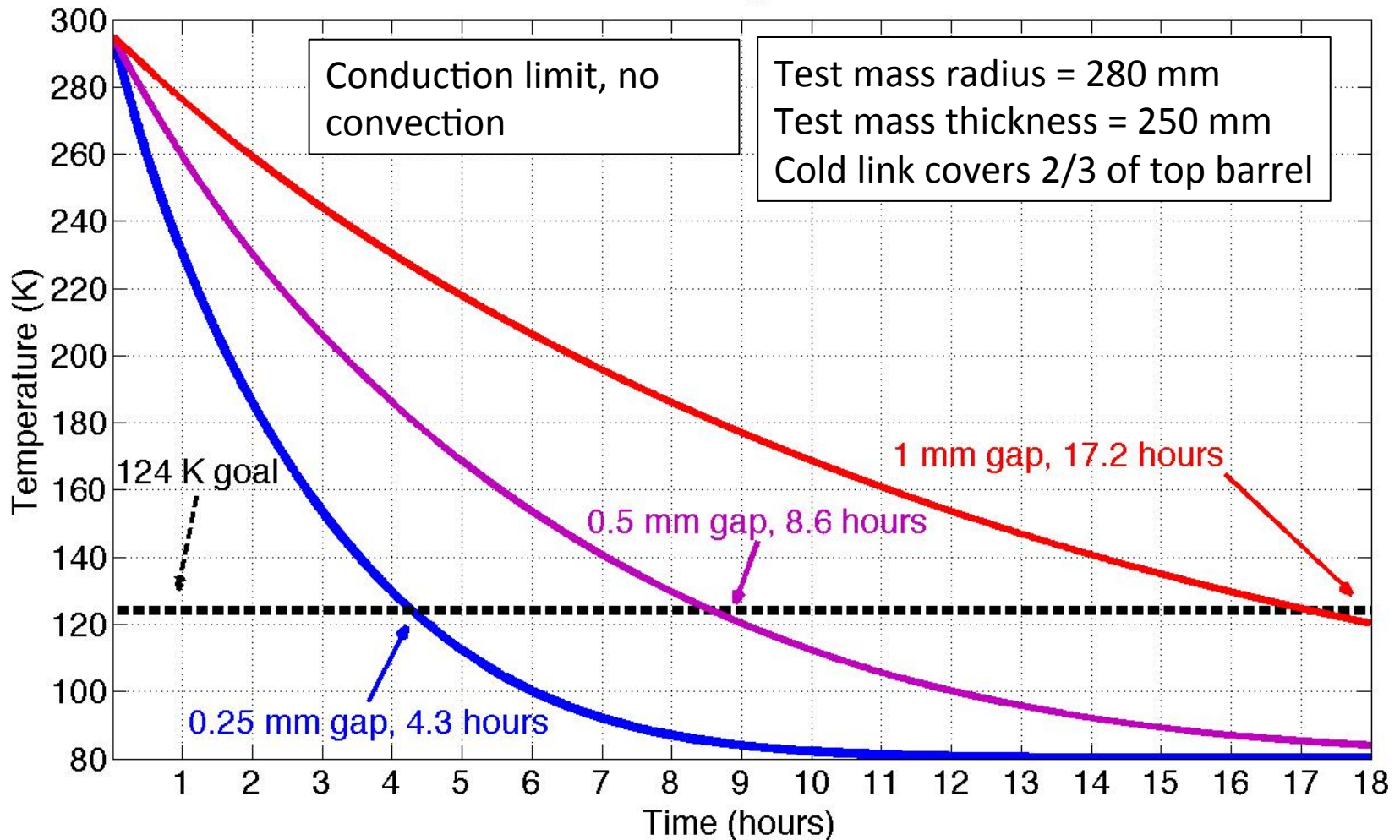
≈ 43 min into cool down



- Convective FEM is proving to require large amounts of computing power

# Cold link on a LIGO III test mass

Cold link on a 143 kg silicon test mass

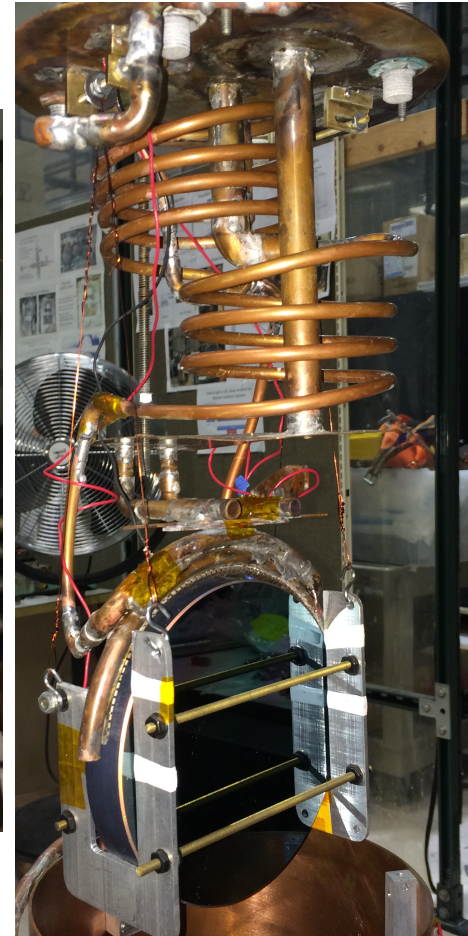
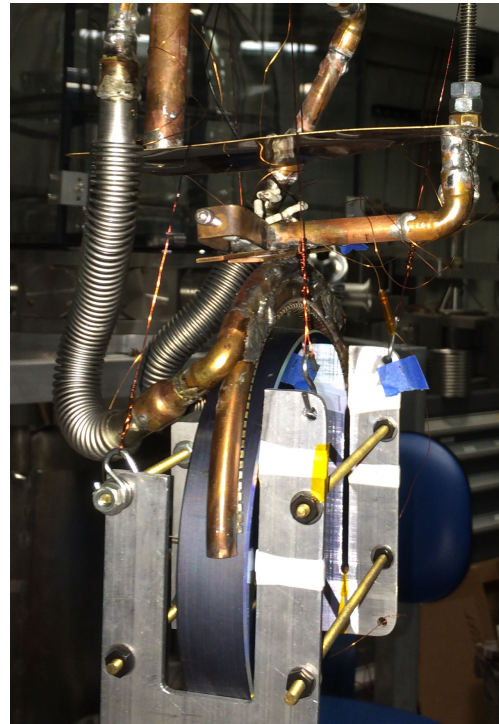


# Experimentation lessons learned

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- Air dominates most heat flow across contacts
- Cold links should have distributed contacts
- Solder is not leak tight against high pressure cryogenic fluids – welding is probably best
- Cryogenic fluid should have 1 flow path
- Send fluid from bottom up
- Use fatter pipes to minimize fluid pressure
- Minimize the number of materials in the plumbing – joining and contraction issues
- Leave room for differential contraction
- Silicon diode temperature sensors are great

# Flexible cold link evolution



# LIGO

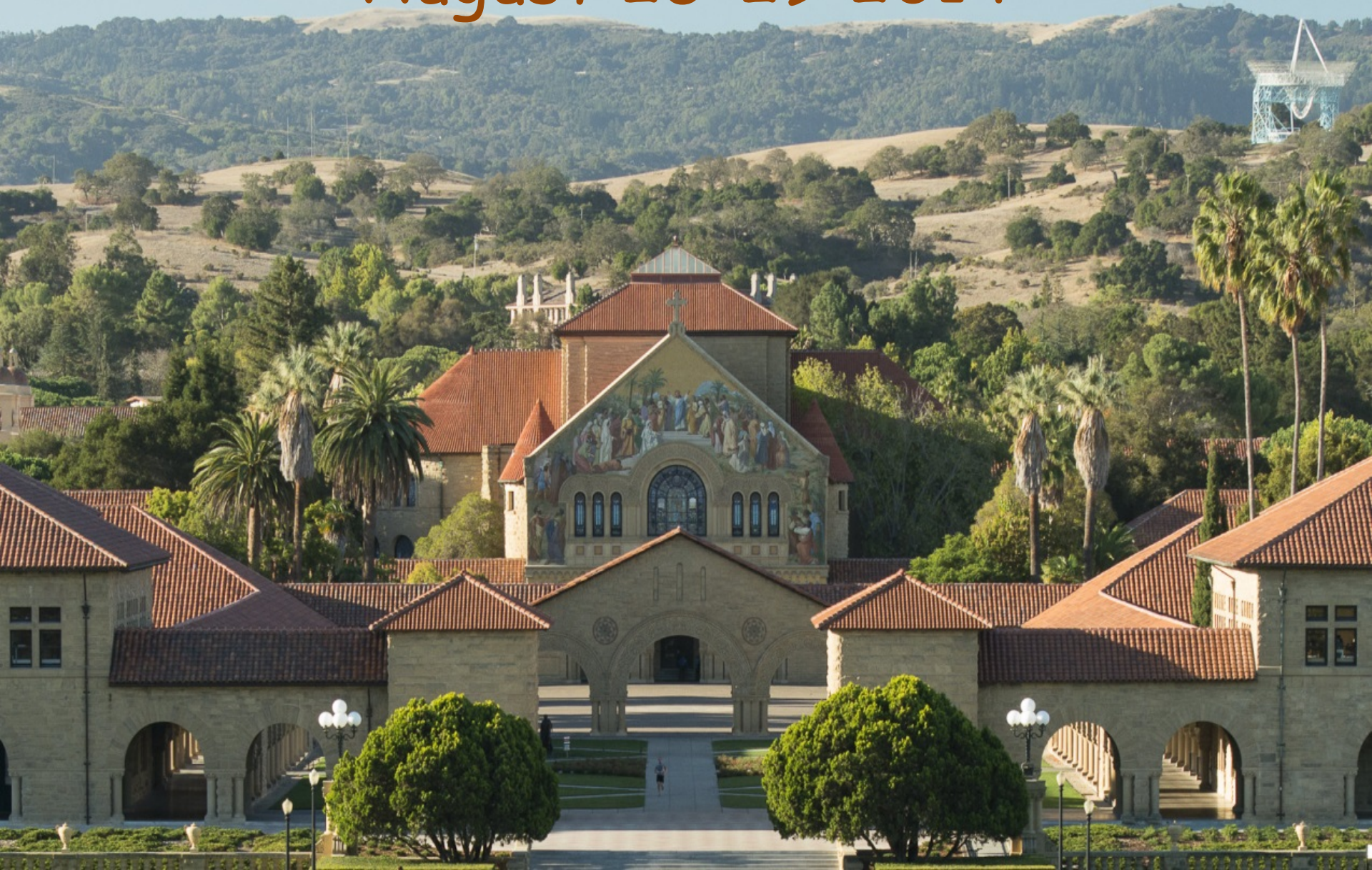
## Future work



- Get bigger pump to reduce pressure
- Better computing for FEM of convection
- Next generation experiment on the prototype aLIGO in-vacuum seismic isolation table.
  - More realistic LIGO setup
  - Measure temperature drifts on LIGO hardware
  - Measure seismic noise of nitrogen delivery
  - Use welded joints to prevent leaks.

# LVC STANFORD

August 25-29 2014





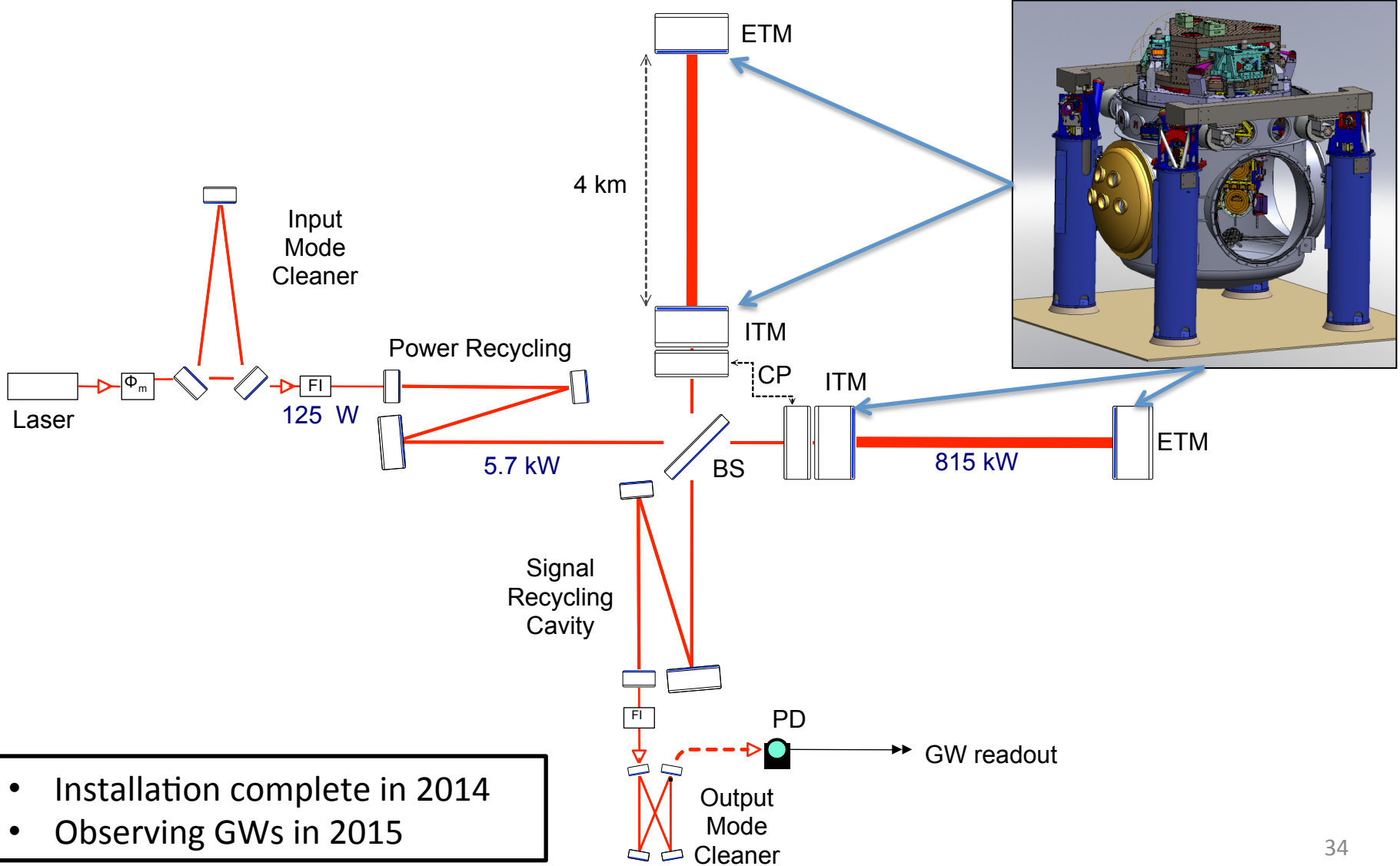
The LIGO logo consists of several concentric, slightly irregular circles in a light gray color, resembling ripples or gravitational waves, positioned in the top-left corner of the slide.

# LIGO



## Backups

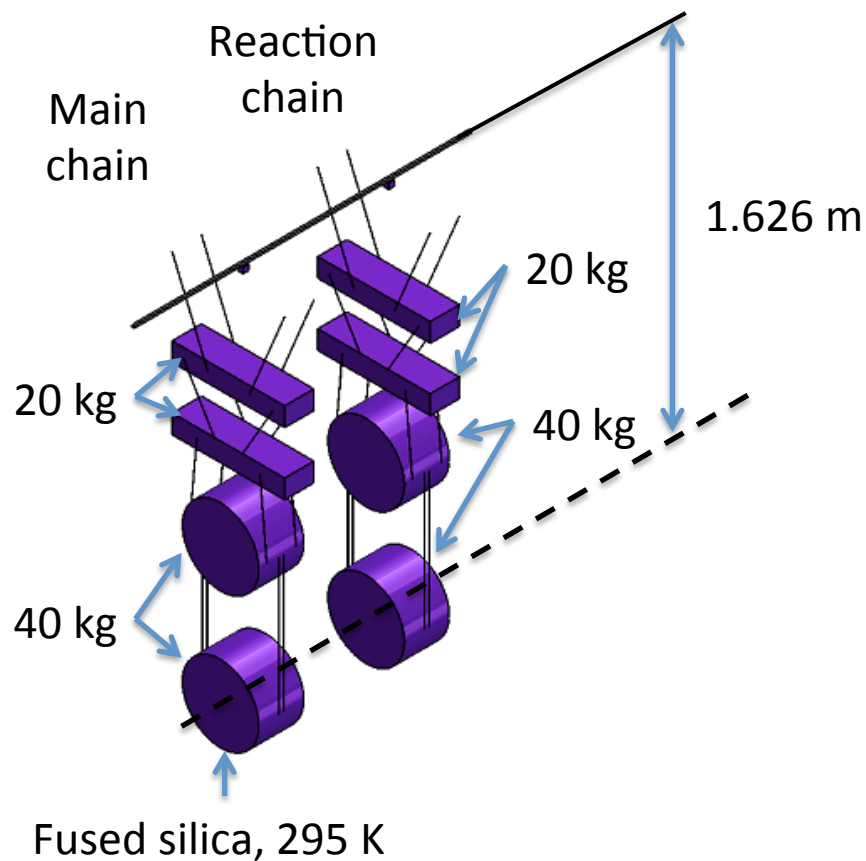
# Advanced LIGO Layout



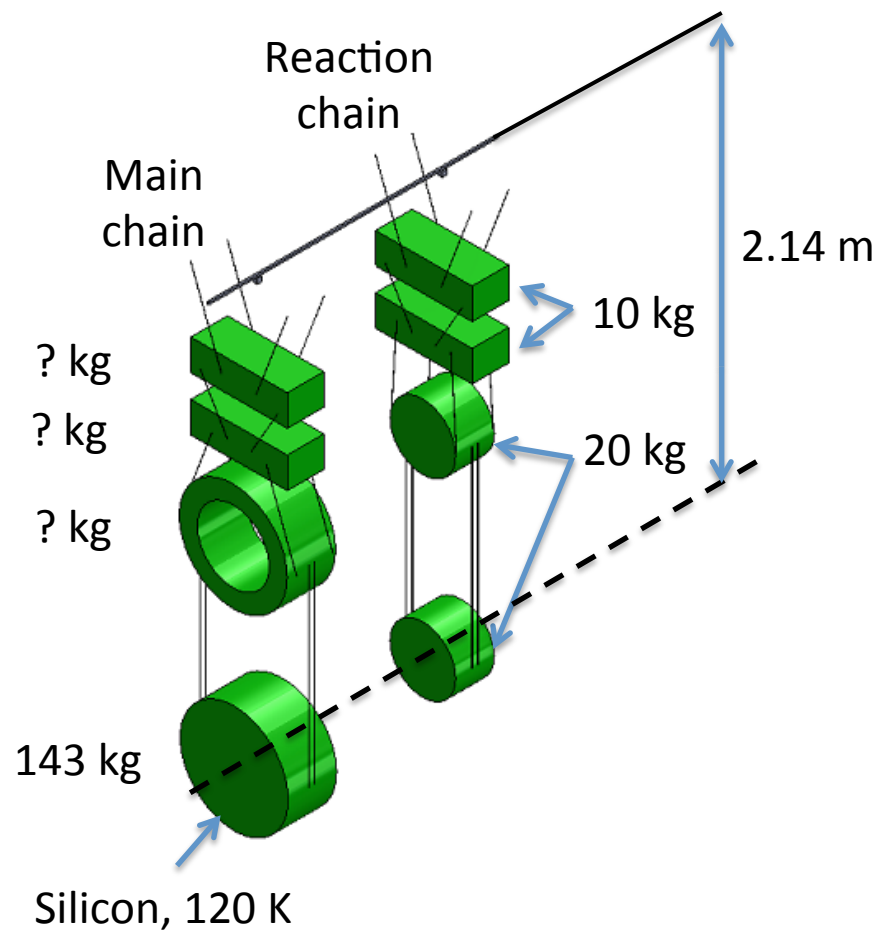
- Installation complete in 2014
- Observing GWs in 2015

# Possible LIGO III Mechanical Upgrades

Advanced LIGO quad pendulum



Preliminary LIGO III quad pendulum



# 3 Quad Conceptual Designs

T1300786

**Higher  
payload**

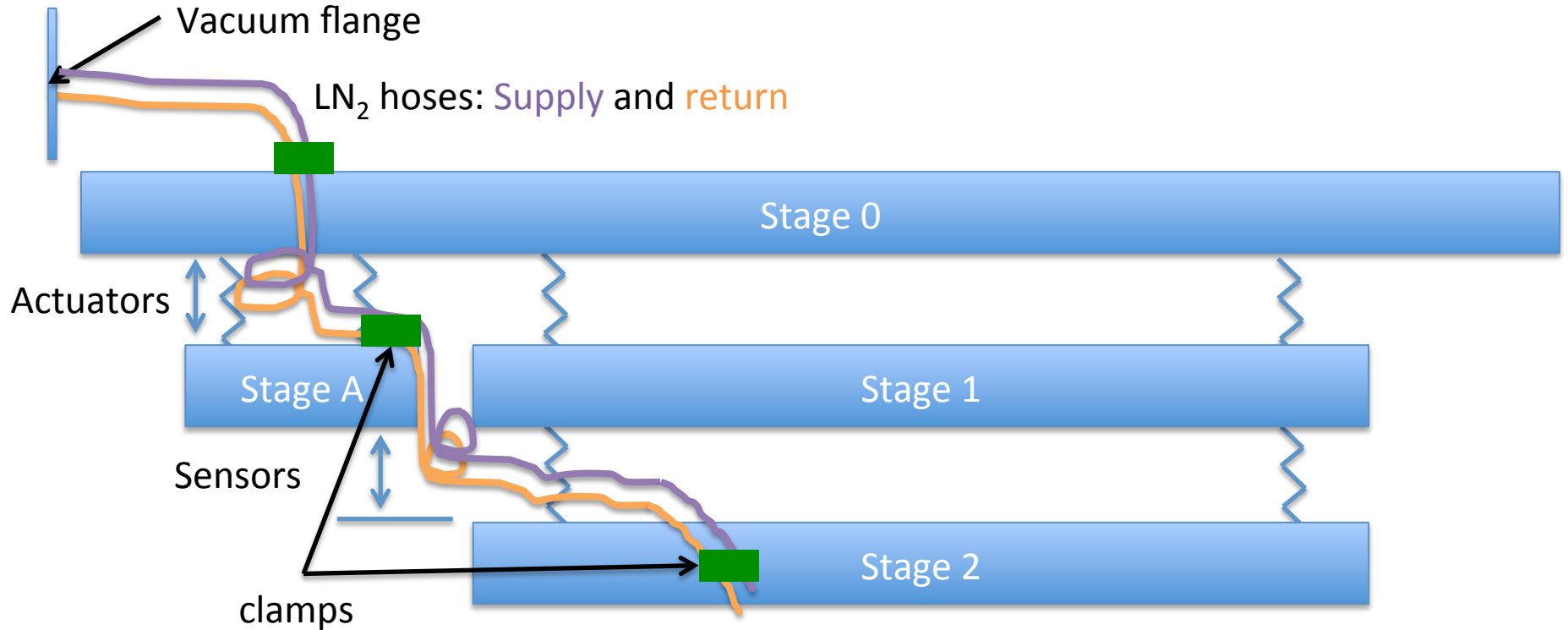
**Lighter  
Test mass**

**Ideal masses with  
PUM springs**

Table 3: Summary of model parameters for the three proposed modifications.

Parameters	Increased $P$	Decreased $m_4$	Penultimate Springs
$P$ , Payload (kg)	301.9	270.0	270.0
$m_1$ (kg)	46.79	41.93	51.55
$m_2$ (kg)	39.54	35.42	41.71
$m_3$ (kg)	72.57	64.86	33.74
$m_4$ (kg)	143.0	127.8	143.0
$L_1$ (m)	0.372	0.372	0.535
$L_2$ (m)	0.372	0.372	0.535
$L_3$ (m)	0.372	0.372	0.535
$L_4$ (m)	1.025	1.025	0.535
long. isolation (m/m)	$1.1 \times 10^{-7}$	$1.1 \times 10^{-7}$	$7.9 \times 10^{-8}$
$f_{bounce}$ (Hz)	9.27	9.27	low, depends on springs
$\sigma_4$ , fiber stress (Mpa)	1400	1400	1400
$E_4$ , fiber modulus (Gpa) [6]	167.4	167.4	167.4
noise budget impact	none	slightly worse	better
relative cost	high	low	high

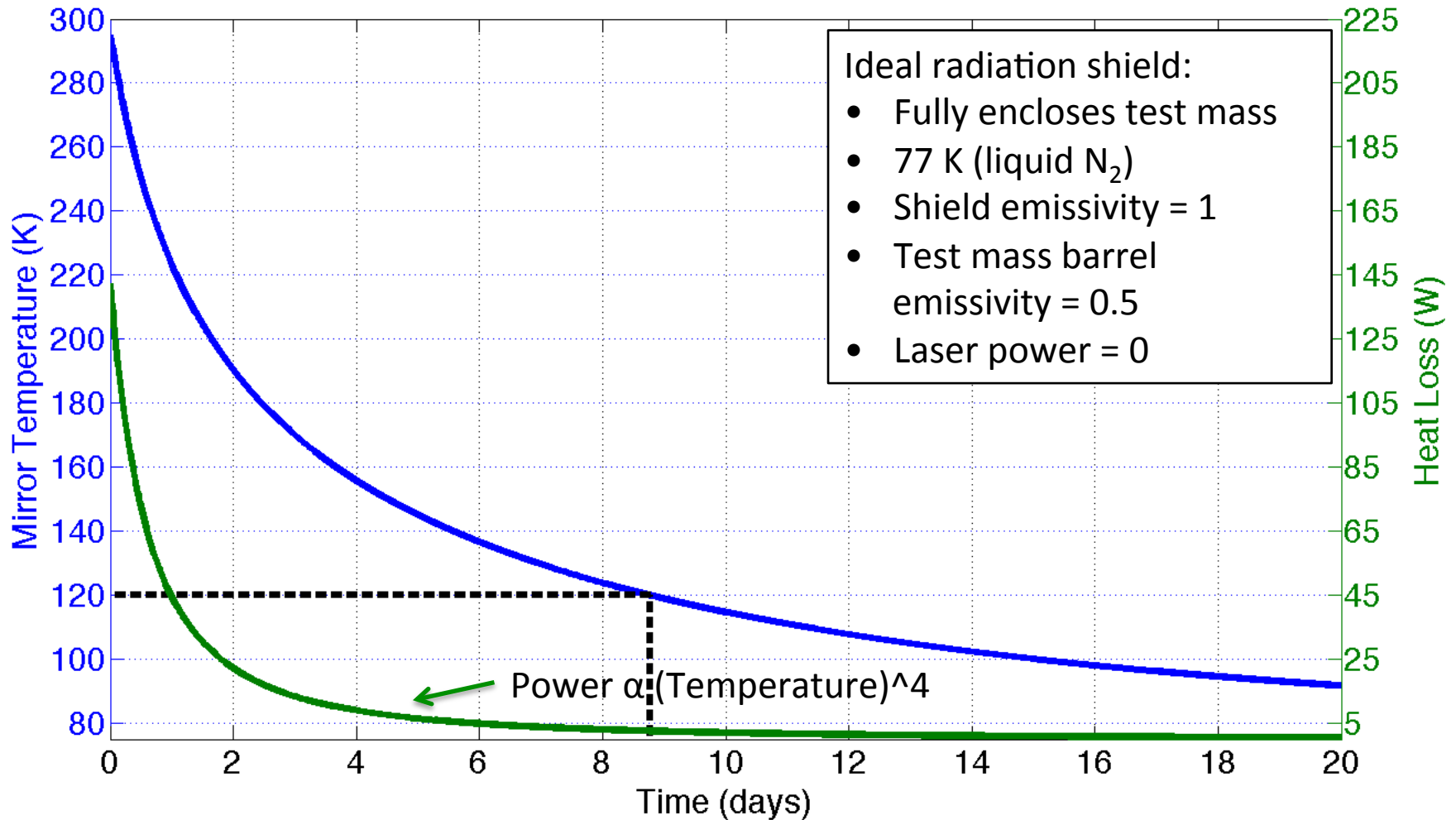
# How to get a LN2 Hose to ST2



Extra stage, A, in parallel with stage 1 carries hose. Stage A is actuated to follow stage 2 so the hose does not short seismic isolation. Stage A sensor noise is set by the stage 2 isolation requirement (so it follows stage 2 and not the sensor noise).

# Test Mass Radiation Simulation

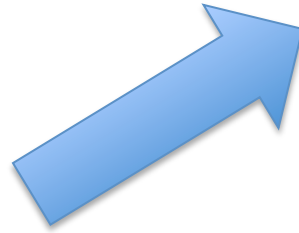
Temperature evolution of a 143 kg silicon test mass. Time to 120 K = 8.7653 days.



# A Lot of Heat to Remove



143 kg Test  
Mass:  
14 MJ to get  
cold (warm)

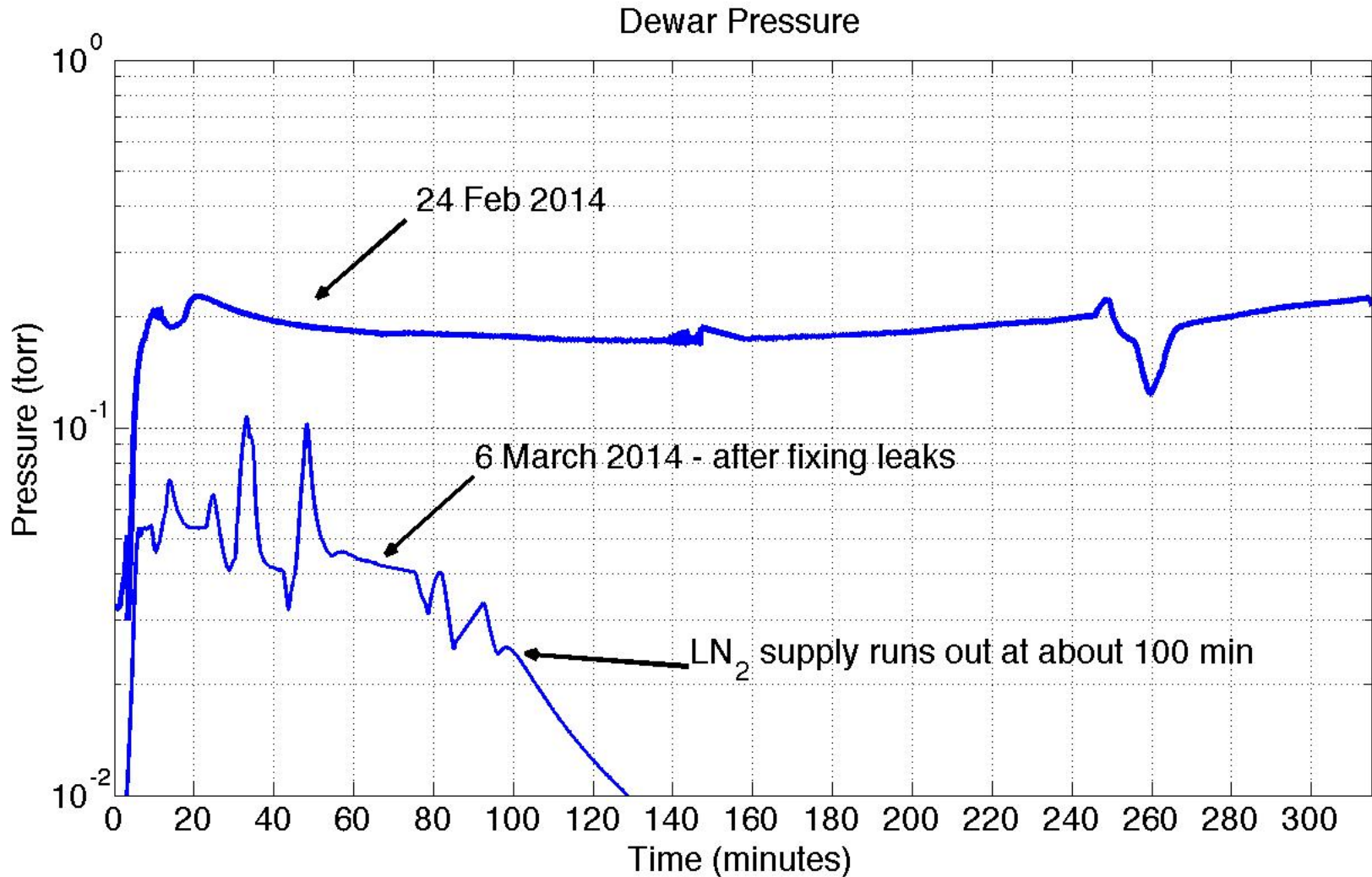


2.7 days to 120 K  
(295 K) at a  
constant 60 W



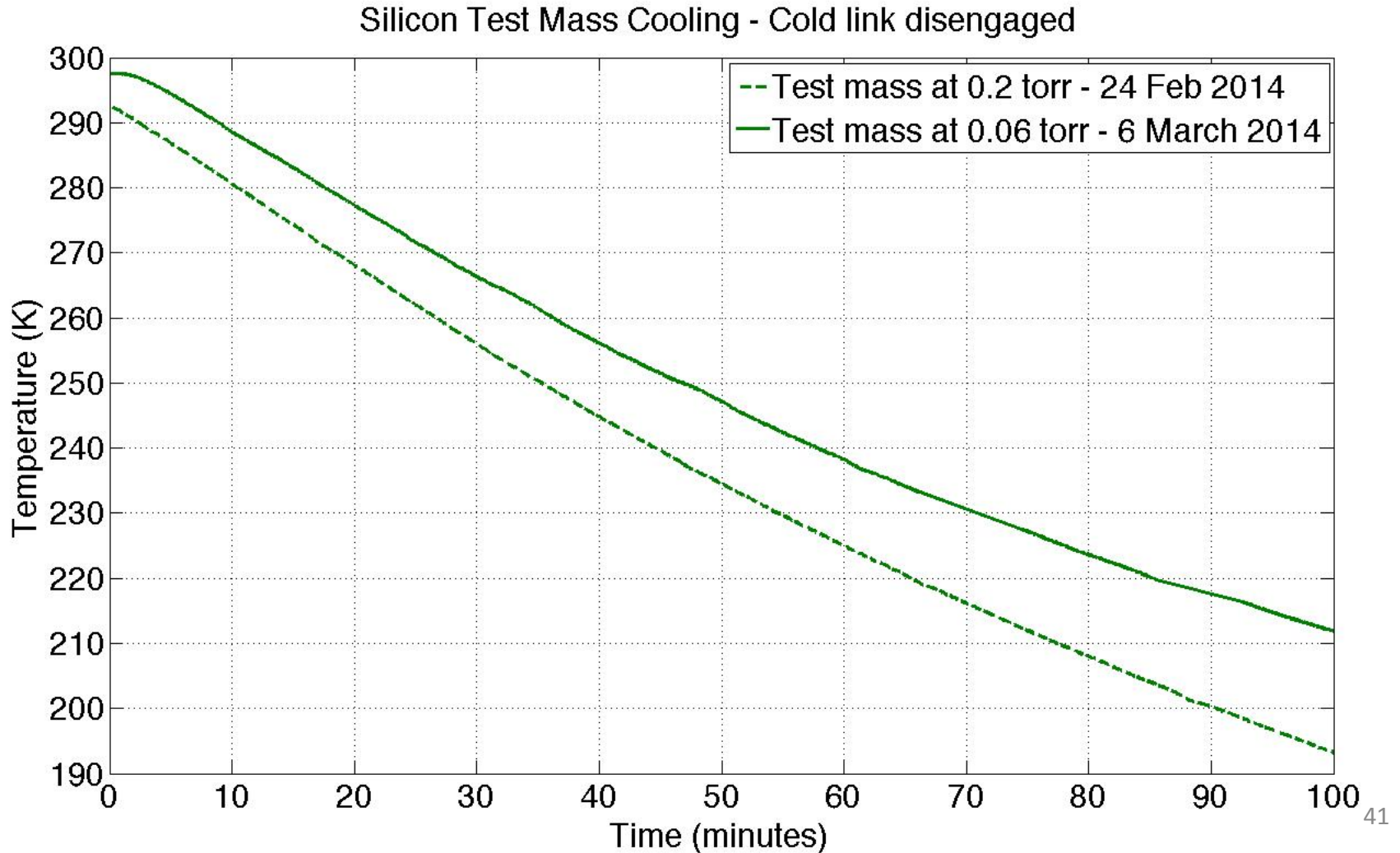
Maybe there is another  
way to cool the test  
mass quickly

# Dewar pressure during measurements

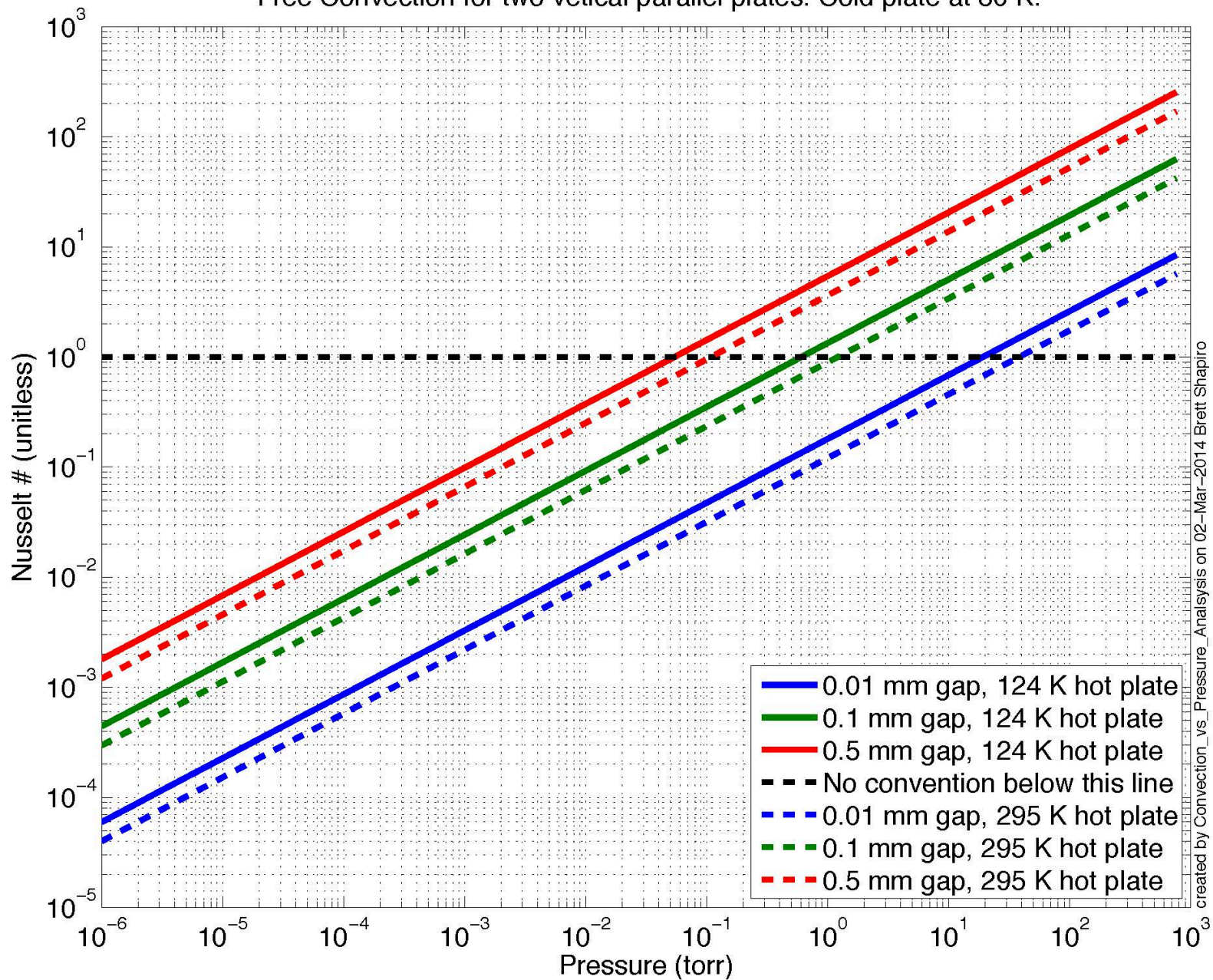




# Effect of pressure on test mass temp



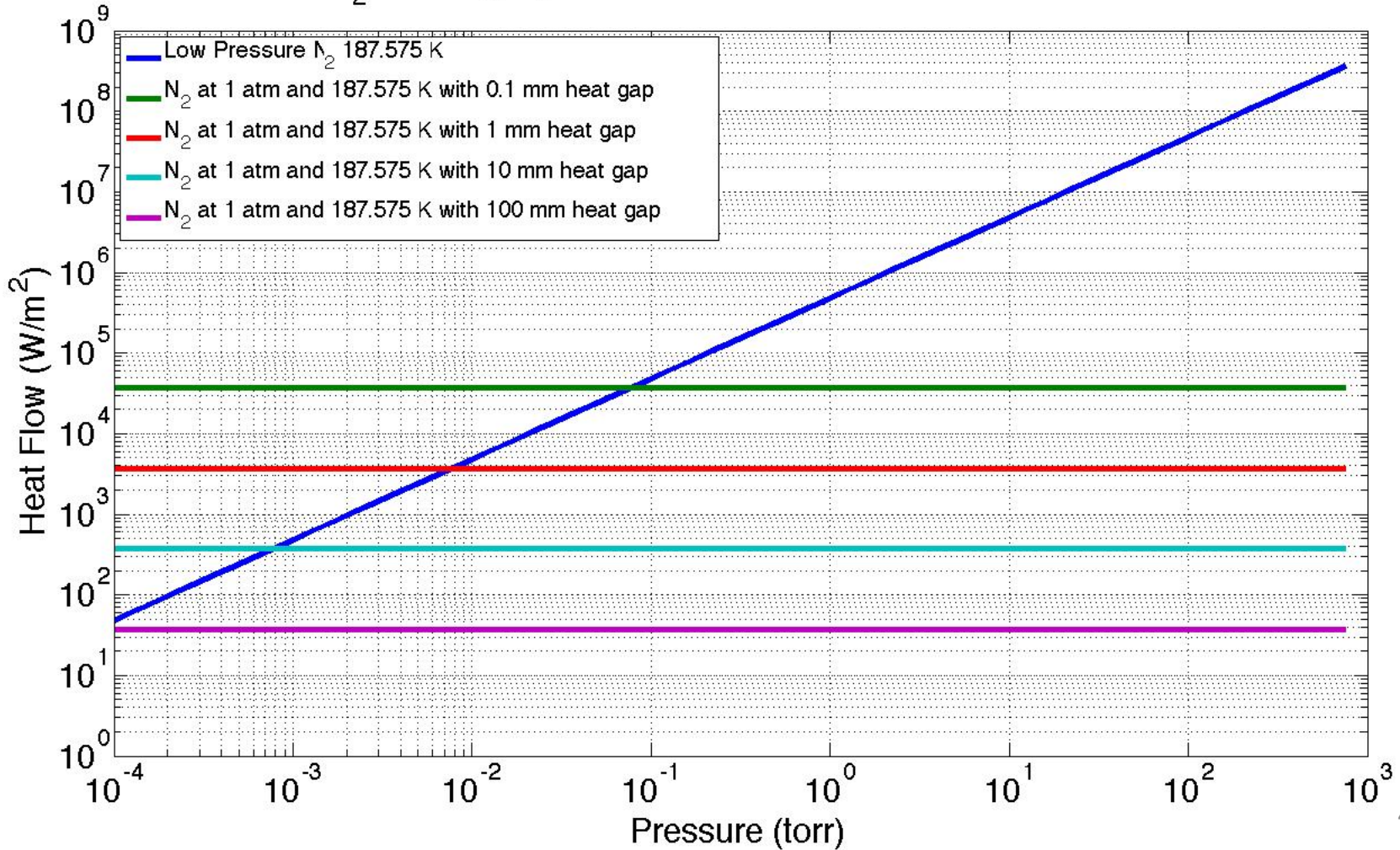
Free Convection for two vertical parallel plates. Cold plate at 80 K.



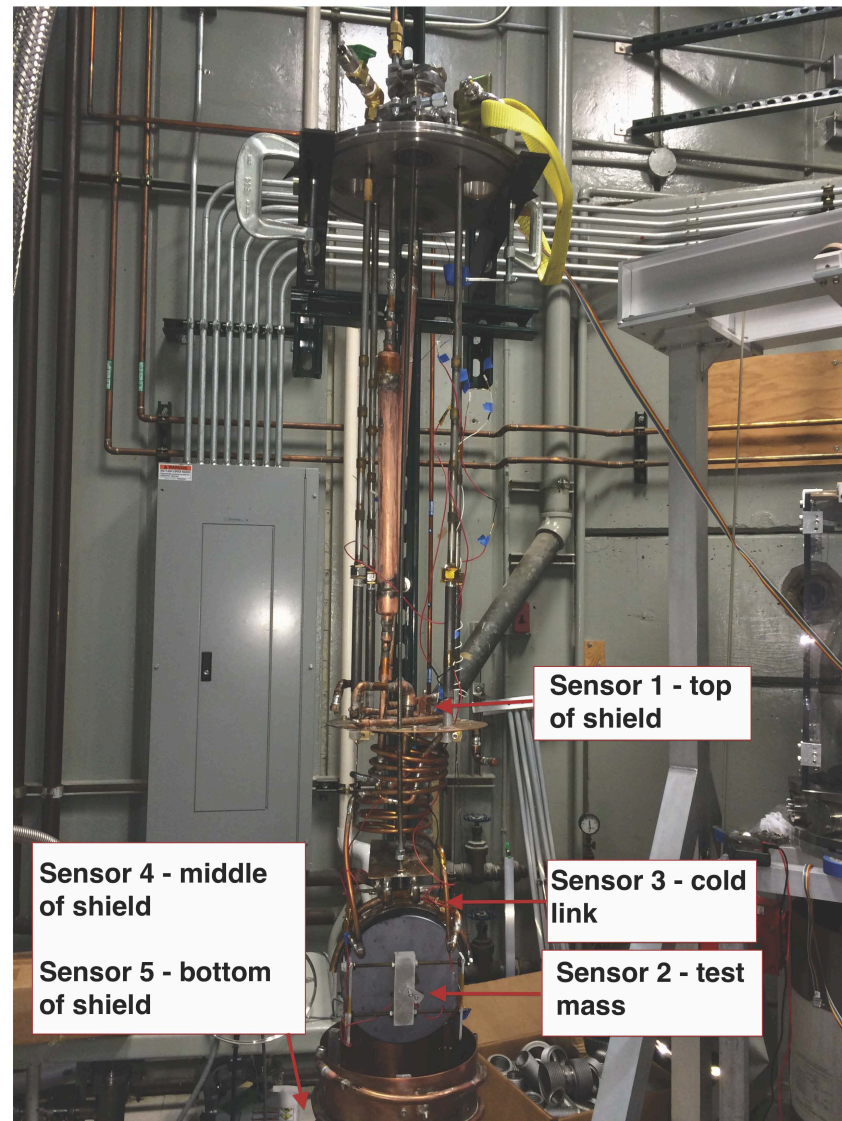
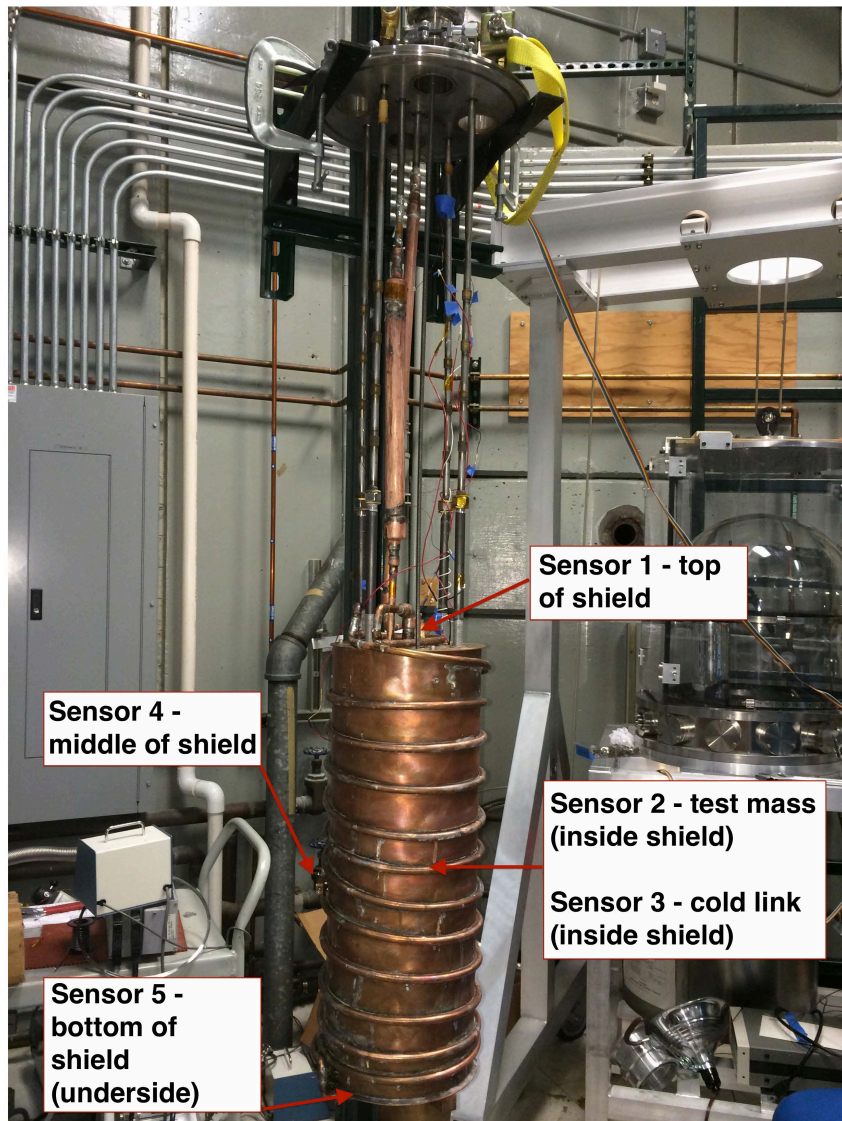
created by Convection\_vs\_Pressure\_Analysis on 02-Mar-2014 Brett Shapiro

# N<sub>2</sub> gas therm. cond. vs pressure

Heat flow with N<sub>2</sub> exchange gas from a 295.15 K test mass to a 80 K heat sink.



# Temperature Sensor Locations



# Test Mass Temperature Equations

$$\dot{Q}_{Si} = K_{CL} \Delta T$$

$$\dot{T}_{Si} = \frac{\dot{Q}_{Si}}{C_{Si}}$$

$$\dot{T}_{Si} = \frac{K_{CL}}{C_{Si}} (T_{cold} - T_{Si})$$

$$\dot{T}_{Si} + \frac{K_{CL}}{C_{Si}} T_{Si} = \frac{K_{CL}}{C_{Si}} T_{cold}$$

$$T_{Si} = T_{hot} e^{-\frac{K_{CL} t}{C_{Si}}} + T_{cold}$$

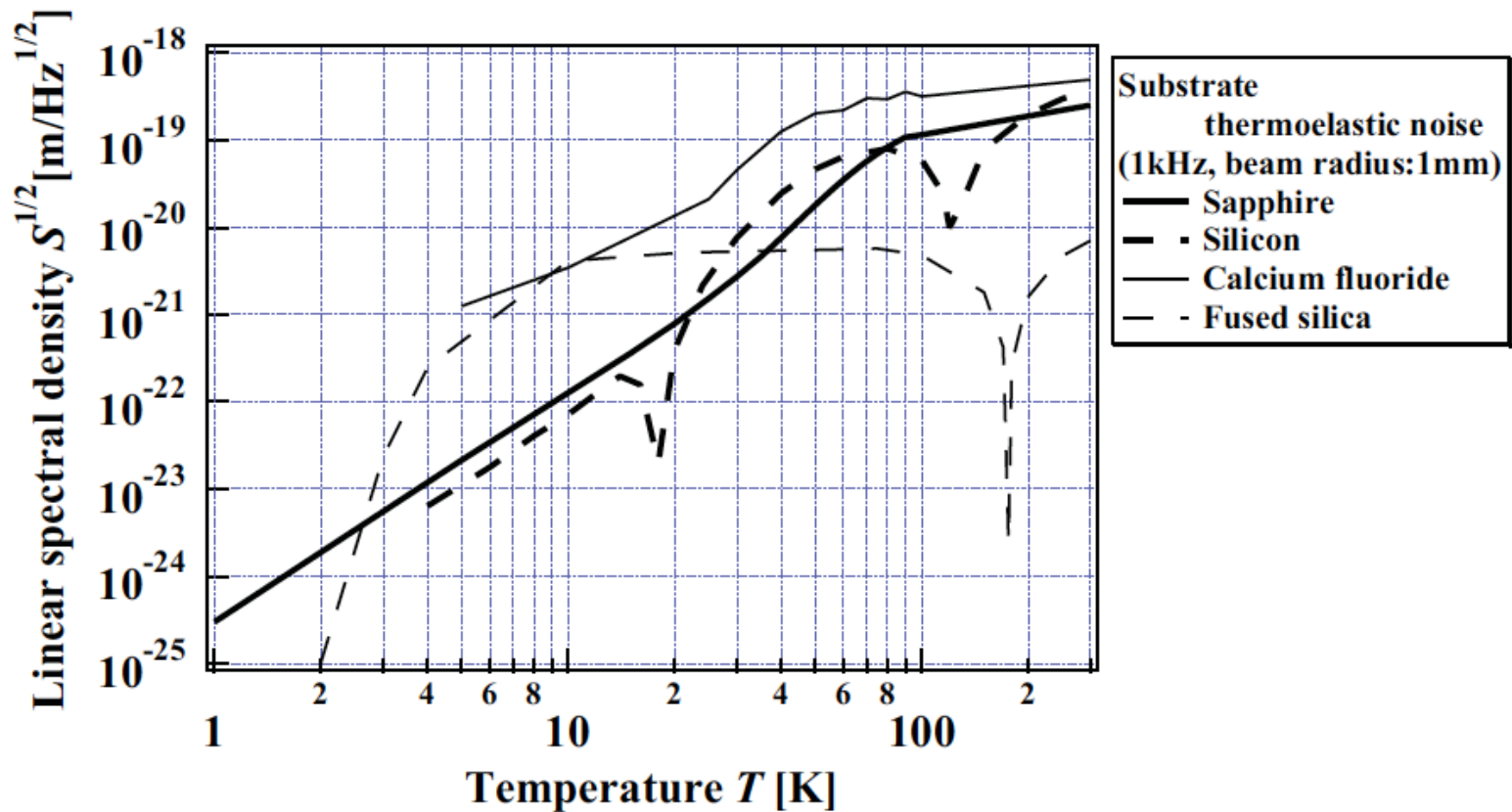
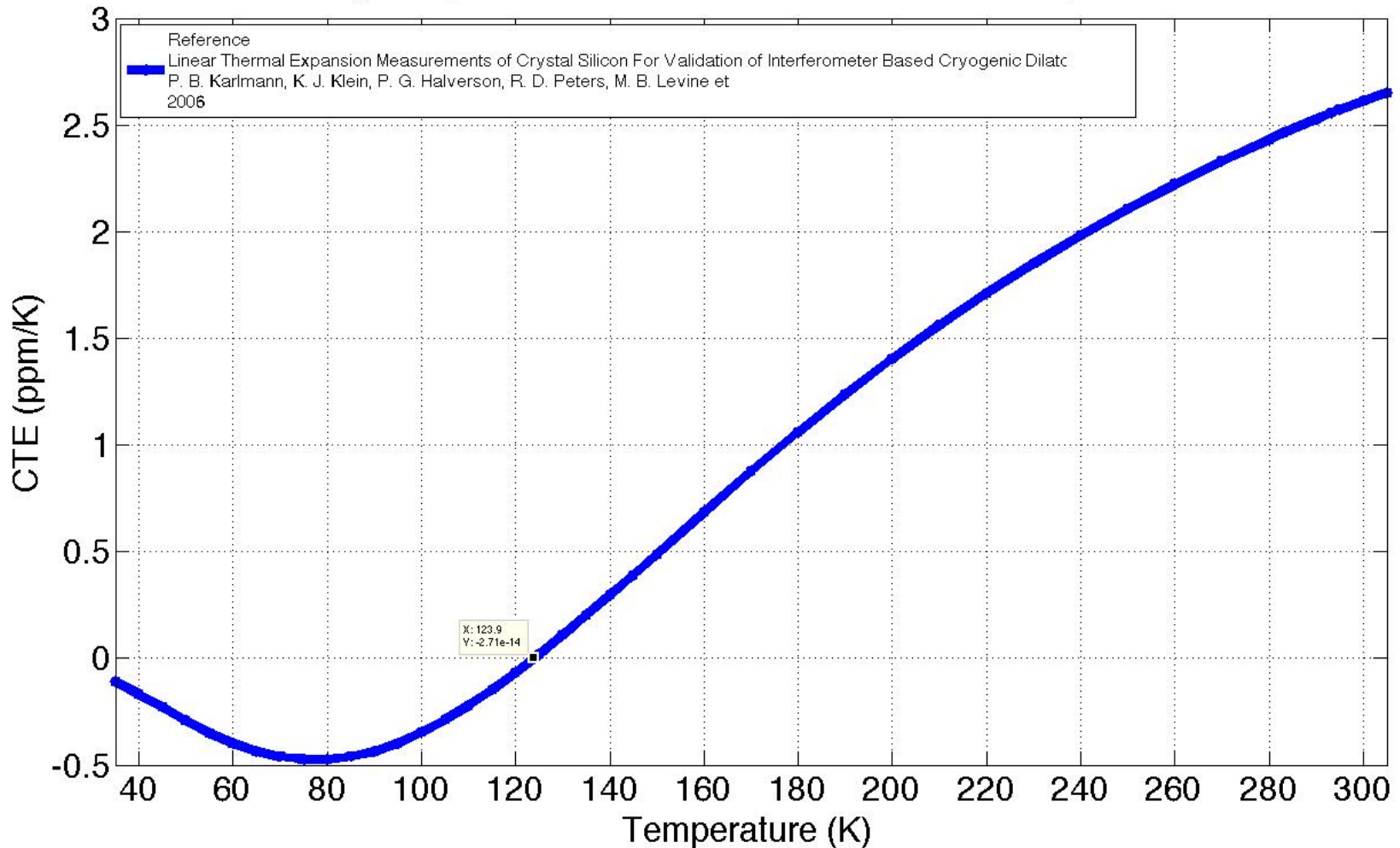


Figure 7.4 Temperature dependence of substrate thermoelastic noise. Frequency  $f$  is 1 kHz and beam radius  $w_0$  is 1 mm.

ref: Harry, Bodiya, Desalvo. Optical Coatings and Thermal Noise in Precision Measurement. 2012. pg 113.

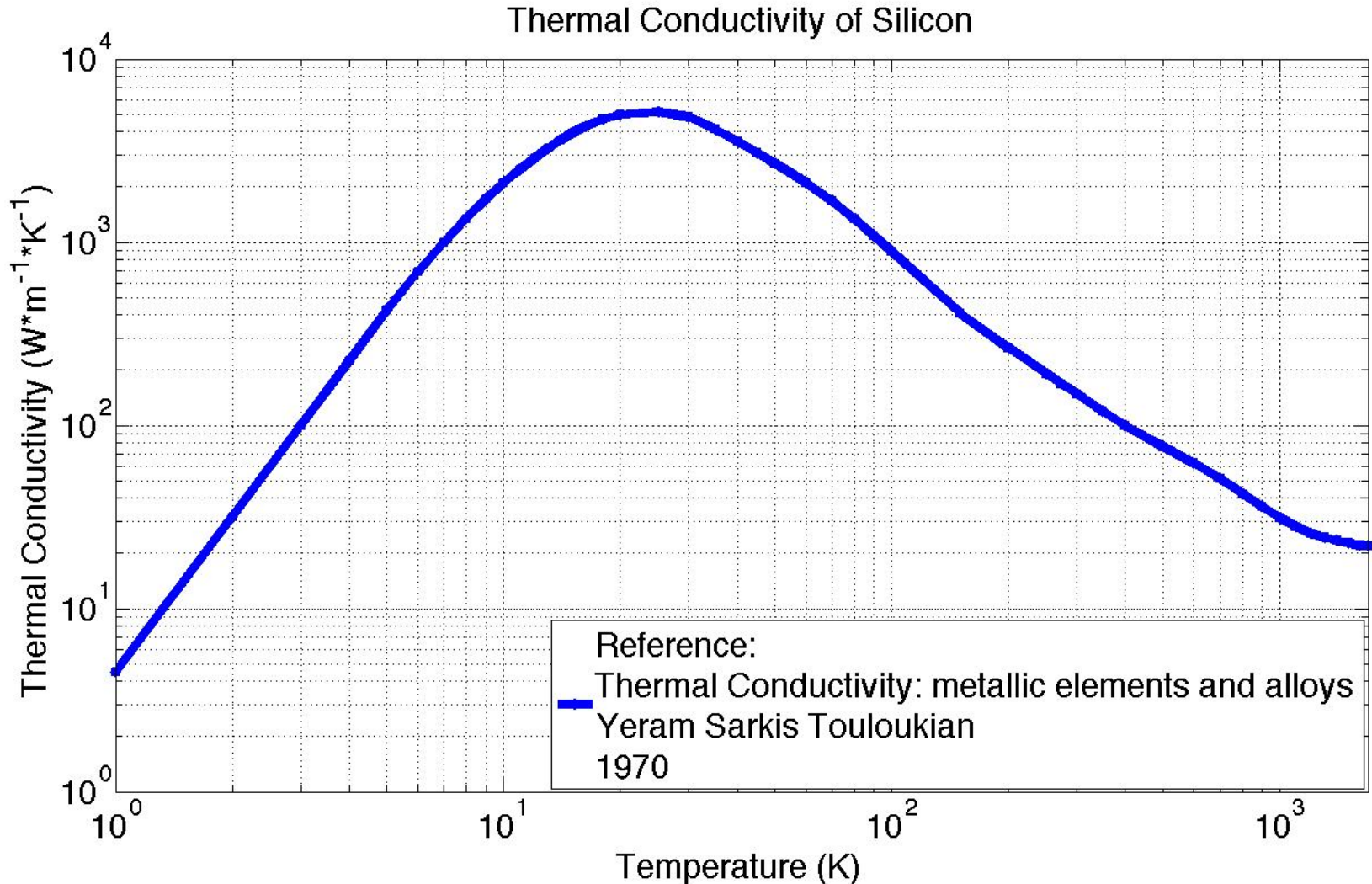
# Si CTE vs Temperature

Single Crystalline Silicon Coefficient of Thermal Expansion



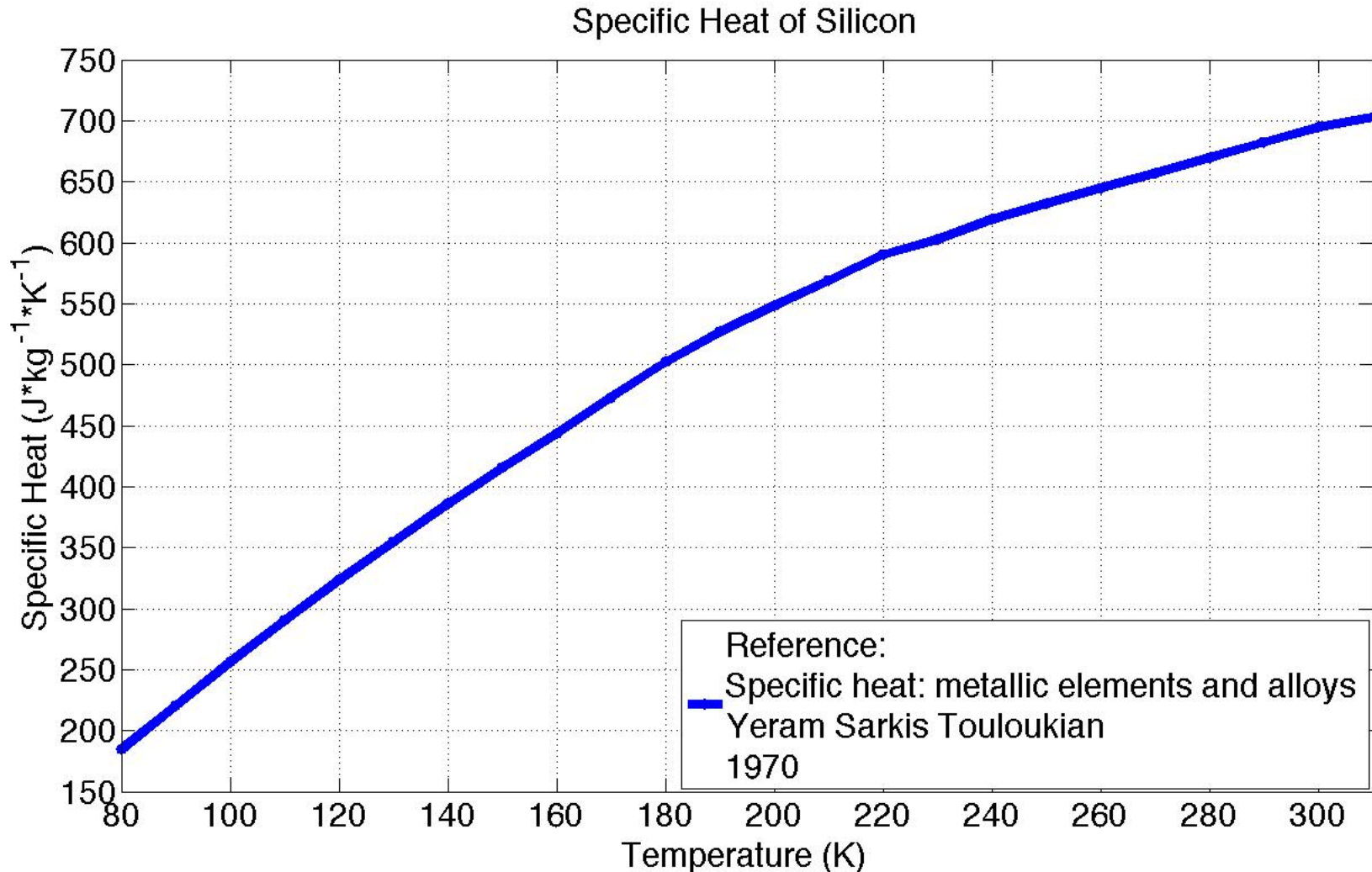
Thermoelastic component of thermal noise goes to zero with CTE.

# Si Thermal Conductivity vs Temp.

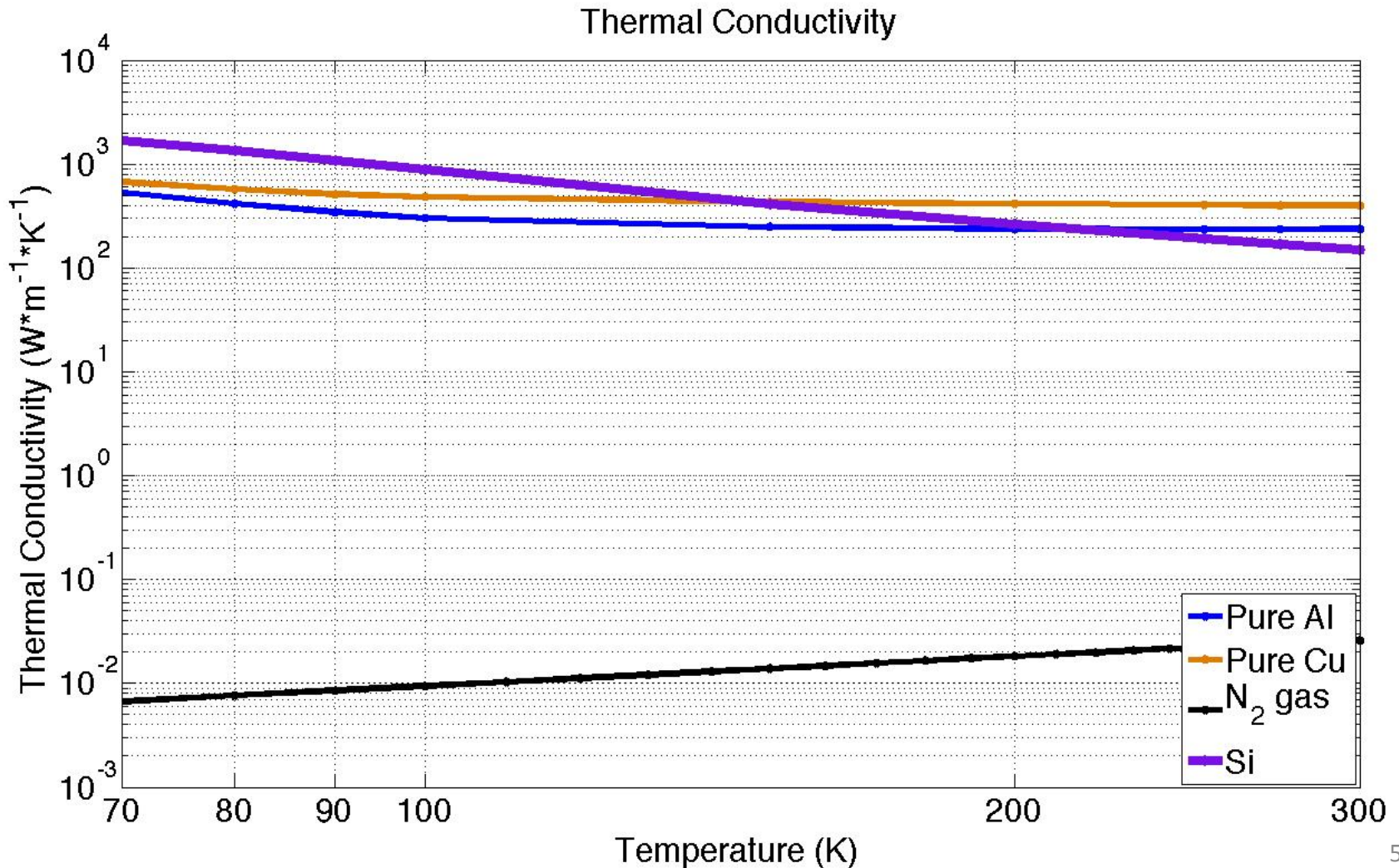




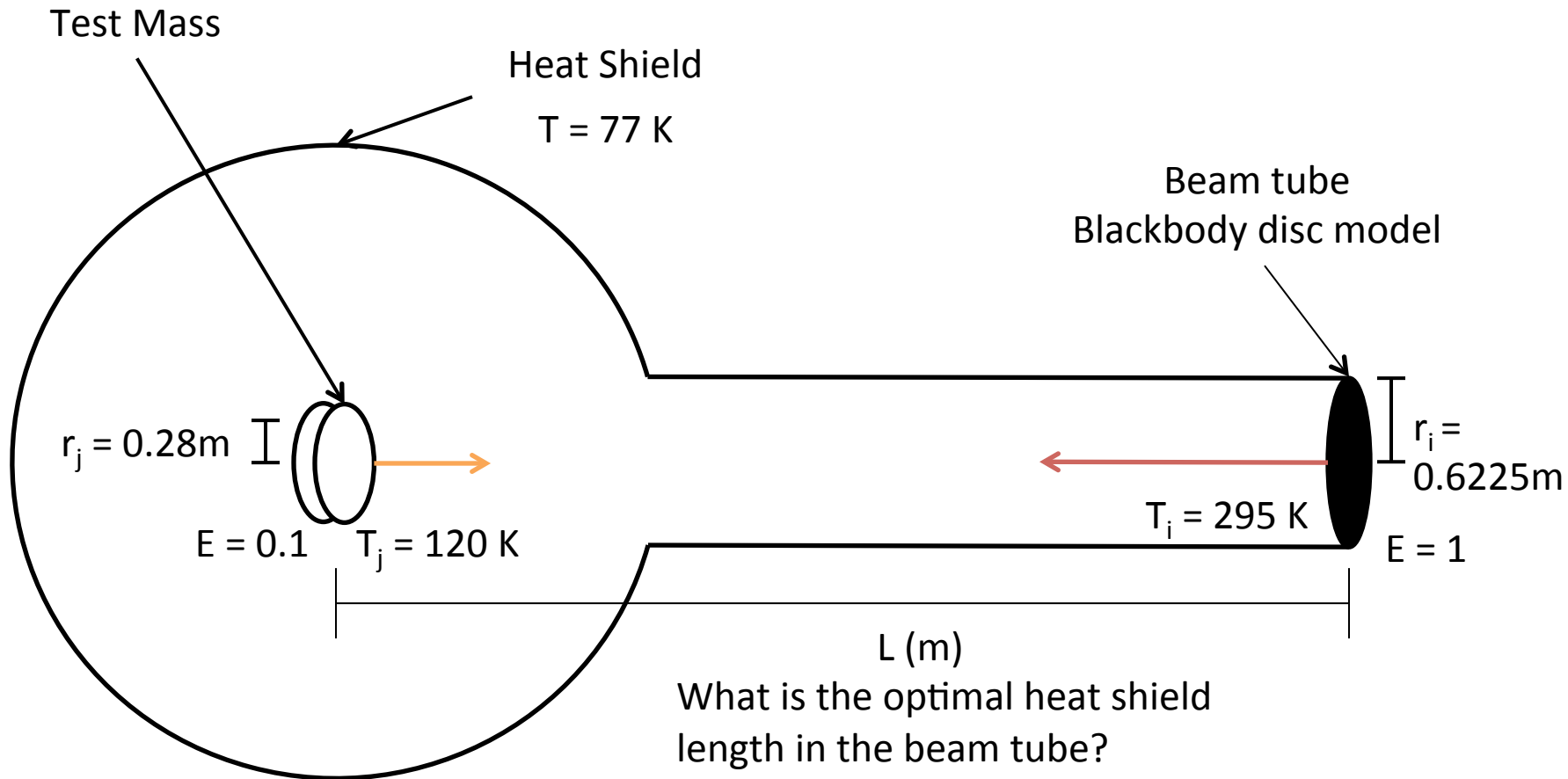
# Si Specific Heat vs Temperature



# Thermal Conductivity of Materials

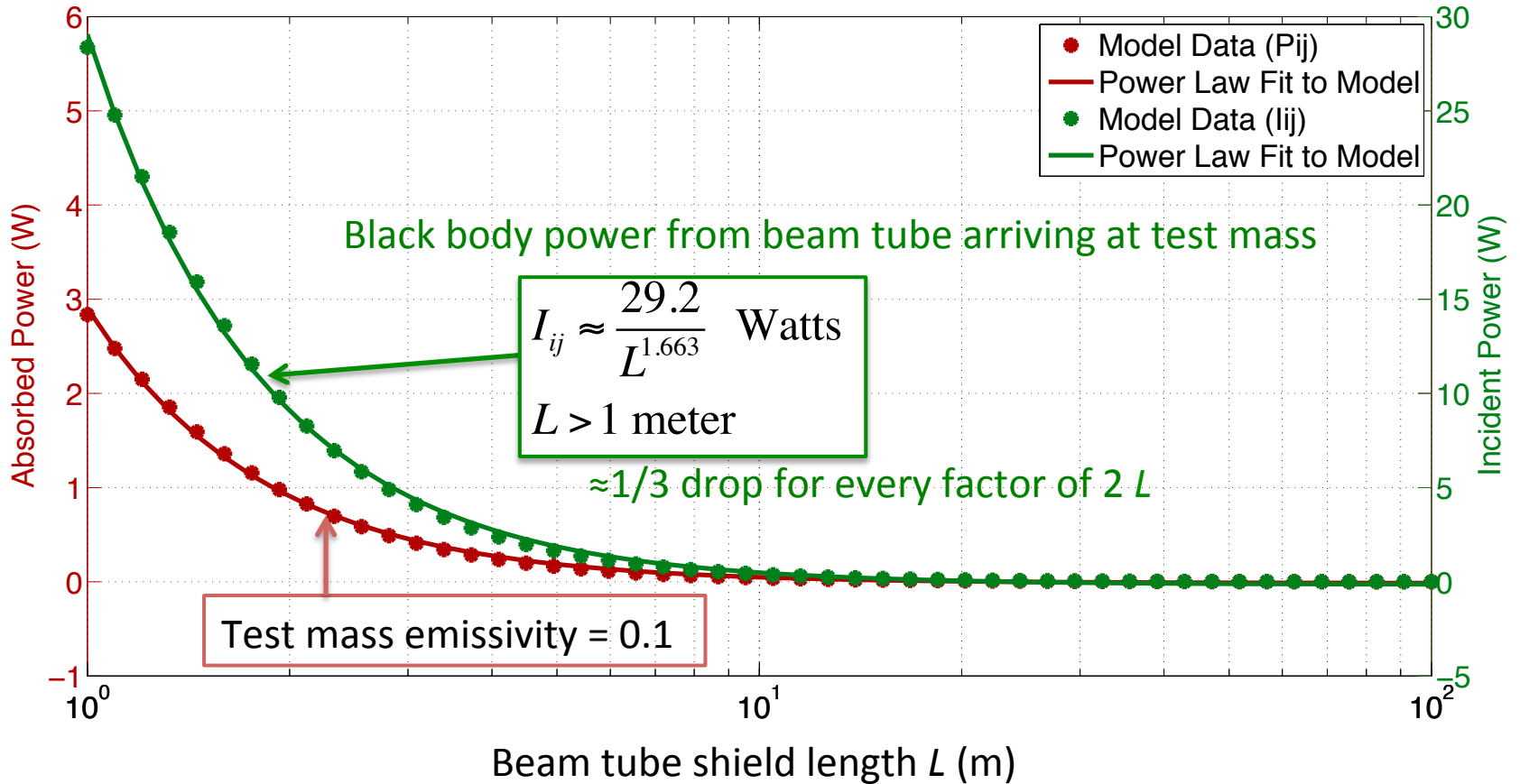


# Beam Tube Heat Shield Length



# Heat shield length in beam tube

Power Absorbed ( $P_{ij}$ ) and Power Incident ( $I_{ij}$ ) on the Test Mass Face from the Beam Tube vs Distance ( $L$ )



# Other Problems To Solve

- Liquid N<sub>2</sub> hoses flexible enough for ISI under vacuum
- Temperature/height control of blade springs
- Test mass temperature control
- How to measure temperature?
  - Measure acoustic modes – Young's modulus is temp. dependent
  - Infrared camera
- Emissivity of optical coatings
- Lossiness of emissive coatings
- Good emissivity estimates/measurements of Si?
- Power absorption in Si (ppm, W, etc)?
- How noisy is bubbling nitrogen: seismic, Newtonian? Do boiling chips help?
- Optical coating thermal noise at 120 K